

DLPC6421 DLP® Display Controller

1 Features

- Dual DLP Controller Support For Up to 4K Ultra High Definition (UHD) Resolution Display Using DLP470TP Digital Micromirror Device (DMD)
 - Up to 4K at 60 Hz
 - Up to 240 Hz at 1080p
 - Up to 120 Hz (3D) at 1080p
- Provides One 60-bit Input Pixel Interface:
 - RGB Data Format
 - 10 Bits per Color
 - Pixel Clock Support Up to 160 MHz for 60-bit
- High-Speed, Low-Voltage Differential Signaling (LVDS) DMD Interface
- Microprocessor Peripherals
 - Three I²C Ports, One UART Port and One SSP Port
 - One USB 1.1 Slave Port
- Image Processing
 - Multiple Image Processing Algorithms
 - Frame Rate Conversion
 - Color Coordinate Adjustment
 - Programmable Color Space Conversion
 - Programmable Degamma and Splash
 - Integrated Support for 3-D Display
 - 1-D Keystone
- Integrated Clock Generation Circuitry
 - Operates on a Single 20-MHz Crystal
 - Integrated Spread Spectrum Clocking

- External Memory Support
 - Parallel Flash for Microprocessor and PWM Sequence
- 516 Pin Plastic Ball Grid Array Package
- Supports LED Systems

2 Applications

- [Mobile Smart TV](#)
- [Mobile Projector](#)
- [Digital Signage](#)
- [Commercial Gaming](#)
- [Smart Home Displays](#)
- [Mobile Home Cinema](#)

3 Description

The DLPC6421 is a digital display controller for the DLP 4K UHD display chipset. The two DLPC6421 display controllers, together with the DLP470TP DMD and DLPA3000/DLPA3005 power management comprise the chipset. This solution is a great fit for display systems that require high resolution and high brightness in a small form factor. To ensure reliable operation, the DLPC6421 display controller must always be used with the DLP470TP DMD and the DLPA3000/DLPA3005 power management integrated circuit.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
DLPC6421	ZPC (516)	27.00 mm x 27.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic

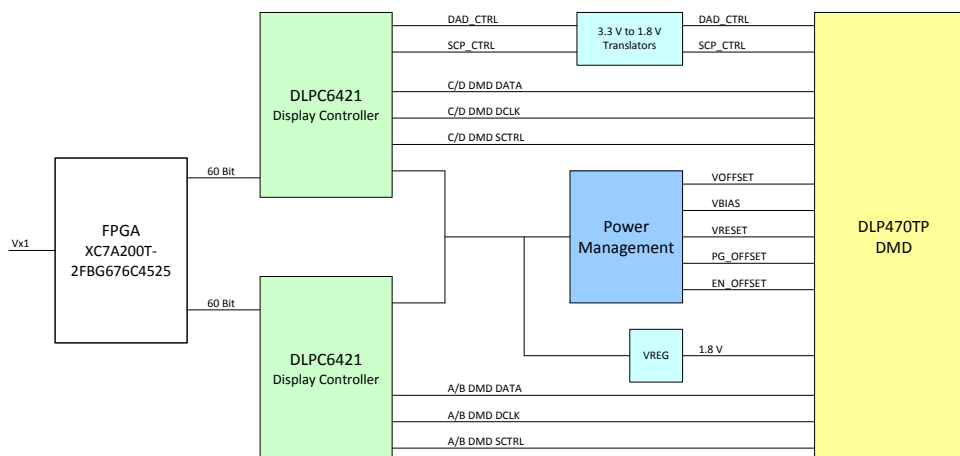


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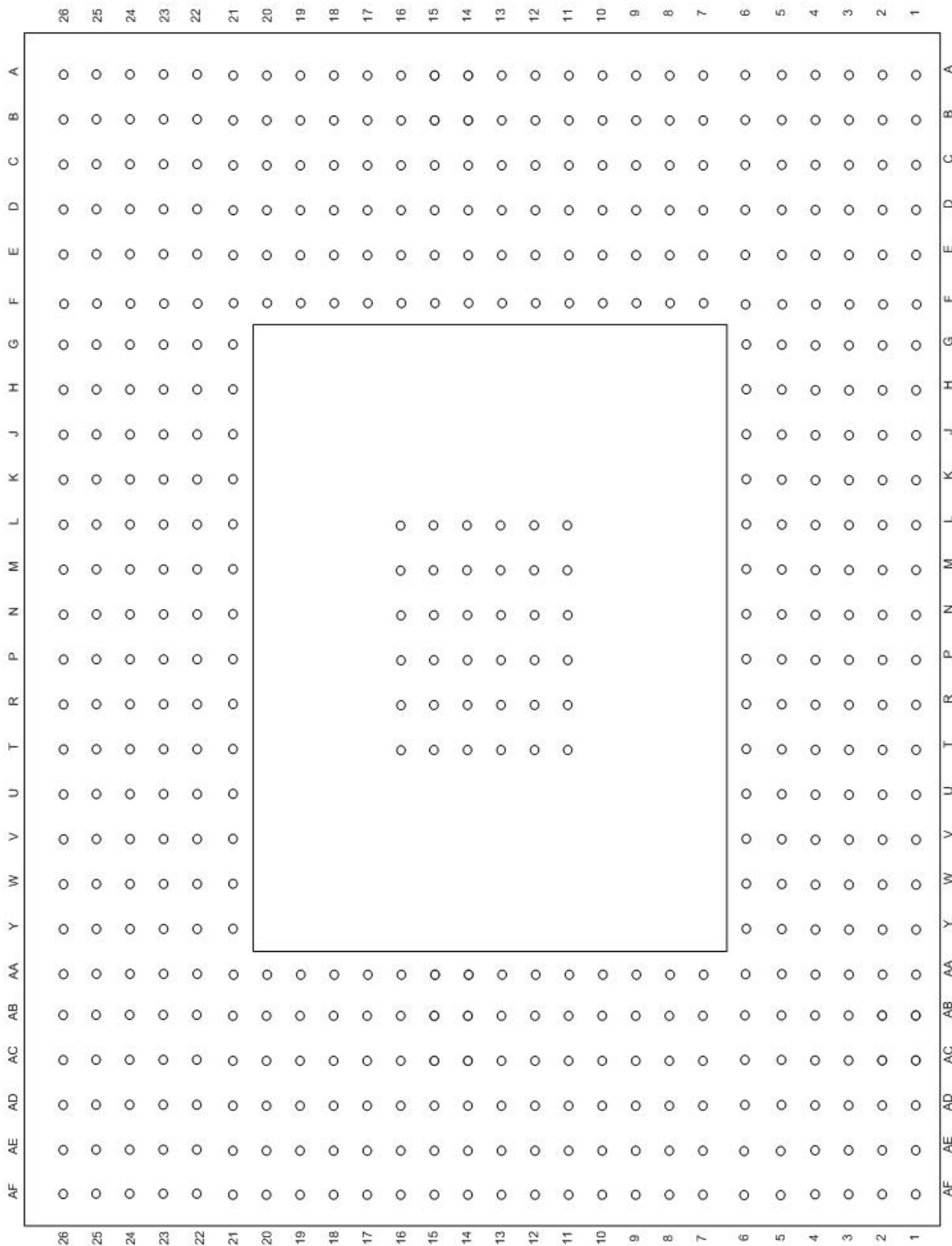
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4 Revision History

DATE	REVISION	NOTES
	*	Initial release.

5 Pin Configuration and Functions

**ZPC Package
516-Pin BGA
Bottom View**



Pin Configurations and Functions

PIN ⁽¹⁾		I/O ⁽²⁾	DESCRIPTION
NAME	NO.		
POSENSE	P22	I ₄	Power-On Sense, High true, signal provided from an external voltage monitor circuit. This signal should be driven active (high) when all DLPC6421 supply voltages have reached 90% of their specified minimum voltage. This signal should be driven inactive (low) after the falling edge of PWRGOOD as specified.
PWRGOOD	T26	I ₄	Power Good, High true, signal from external power supply or voltage monitor. A high value indicates all power is within operating voltage specs and the system is safe to exit its reset state. A transition from high to low is used to indicate that the controller or DMD supply voltage will drop below their rated minimum level. This transition must occur prior to the supply voltage drop as specified. During this interval, POSENSE must remain active high. This is an early warning of an imminent power loss condition. This warning is required to enhance long term DMD reliability. A DMD park followed by a full controller reset is performed by the DLPC6421 controller when PWRGOOD goes low for the specified minimum, protecting the DMD. This minimum de-assertion time is used to protect the input from glitches. Following this the DLPC6421 controller will be held in its reset state as long as PWRGOOD is low. PWRGOOD must be driven high for normal operation. The DLPC6421 controller will acknowledge PWRGOOD as active once it's been driven high for its specified minimum time. Uses hysteresis.
EXT_ARTZ	T24	O ₂	General purpose, LOW true, reset output. This output is asserted low immediately upon asserting power-up reset (POSENSE) low and remains low while POSENSE remains low. EXT_ARSTZ continues to be held low after the release of power-up reset (that is, POSENSE set high) until released by software. EXT_ARSTZ is also asserted low approximately 5 μs after the detection of a PWRGOOD or any internally generated reset. In all cases it will remain active for a minimum of 2 ms. Note that the DLPC6421 contains a software register that can be used to independently drive this output.
MTR_ARTZ	T25	O ₂	Reserved
BOARD LEVEL TEST AND INITIALIZATION⁽³⁾			
TDI	N25	I ₄	JTAG serial data in
TCK	N24	I ₄	JTAG serial data clock
TMS1	P25	I ₄	JTAG test mode select
TMS2	P26	I ₄	JTAG test mode select
TDO1	N23	O ₅	JTAG serial data out
TDO2	N22	O ₅	JTAG serial data out
TRSTZ	M23	I ₄	JTAG reset. This signal includes an internal pull-up and utilizes hysteresis. This pin should be pulled high (or left unconnected) when the JTAG interface is in use for boundary scan or ARM debug. Connect this pin to ground otherwise. Failure to tie this pin low during normal operation will cause startup and initialization problems.
RTCK	E4	O ₂	JTAG return clock
ETM_PIPESTAT_2	A4	B ₂	ETM trace port pipeline status. Indicates the pipeline status of the ARM core. These signals include internal pull-downs.
ETM_PIPESTAT_1	B5	B ₂	
ETM_PIPESTAT_0	C6	B ₂	
ETM_TRACESYNC	A5	B ₂	ETM trace port synchronization signal, indicating the start of a branch sequence on the trace packet port. This signal includes an internal pull-down.
ETM_TRACECLK	D7	B ₂	ETM trace port clock. This signal includes an internal pull-down.
ICTSEN	M24	I ₄	IC tri-State enable (active high). Asserting high will tri-state all outputs except the JTAG interface. This signal includes an internal pull-down however TI recommends an external pull-down for added protection. Uses hysteresis.
TSTPT_7	E8	B ₂	Test pin 7 - This signal provides internal pull-downs. Normal use: reserved for test output. Should be left open or unconnected for normal use.
TSTPT_6	B4	B ₂	Test pin 6 - This signal provides internal pull-downs. Normal use: reserved for test output. Should be left open or unconnected for normal use.
TSTPT_5	C4	B ₂	Test pin 5 - This signal provides internal pull-downs. Normal use: reserved for test output. Should be left open or unconnected for normal use.
TSTPT_4	E7	B ₂	Test pin 4 - This signal provides internal pull-downs. Normal use: reserved for test output. Should be left open or unconnected for normal use.
TSTPT_3	D5	B ₂	Test pin 3 - This signal provides internal pull-downs. Normal use: reserved for test output. Should be left open or unconnected for normal use.
TSTPT_2	E6	B ₂	Test pin 2 - This signal provides internal pull-downs. Additionally, TI recommends that jumper options be provided for connecting TSTPT(2:0) to external pull-ups.

(1) For instructions on handling unused pins, see [General Handling Guidelines for Unused CMOS-type Pins](#).

(2) I/O Type: I = Input, O = Output, B = Bidirectional, and H = Hysteresis. See [Table 1](#) for subscript explanation.

(3) All JTAG signals are LVTTTL compatible.

Pin Configurations and Functions (continued)

PIN ⁽¹⁾		I/O ⁽²⁾	DESCRIPTION
NAME	NO.		
TSTPT_1	D3	B ₂	Test pin 1 - This signal provides internal pull-downs. Additionally, TI recommends that jumper options be provided for connecting TSTPT(2:0) to external pull-ups.
TSTPT_0	C2	B ₂	Test pin 0 - This signal provides internal pull-downs. Additionally, TI recommends that jumper options be provided for connecting TSTPT(2:0) to external pull-ups.
DEVICE TEST			
HW_TEST_EN	M25	I ₄	Device manufacturing test enable; This signal includes an internal pull-down and utilizes hysteresis. TI recommends that this signal be tied to an external ground in normal operation for added protection.
ANALOG FRONT END			
AFE_ARSTZ	AC12	O ₂	Reserved
AFE_CLK	AD12	O ₆	Reserved
AFE_JRQ	AB13	I ₄	Reserved
PORT1 and PORT 2 CHANNEL DATA and CONTROL⁽⁴⁾⁽⁵⁾⁽⁶⁾⁽⁷⁾			
P_CLK1	AE22	I ₄	Input port data pixel write clock (selectable as rising or falling edge triggered, and which port it is associated with (A or B or (A and B))). This signal includes an internal pull-down.
P_CLK2	W25	I ₄	Input port data pixel write clock (selectable as rising or falling edge triggered, and which port it is associated with (A or B or (A and B))). This signal includes an internal pull-down.
P_CLK3	AF23	I ₄	Input port data pixel write clock (selectable as rising or falling edge triggered, and which port it is associated with (A or B or (A and B))). This signal includes an internal pull-down.
P_DATAEN1	AF22	I ₄	Active high data enable. Selectable as to which port it is associated with (A or B or (A and B)). This signal includes an internal pull-down.
P_DATAEN2	W24	I ₄	Active high data enable. Selectable as to which port it is associated with (A or B or (A and B)). This signal includes an internal pull-down.
P1_A_9	AD15	I ₄	Port 1 A Channel Input Pixel Data (bit weight 128)
P1_A_8	AE15	I ₄	Port 1 A Channel Input Pixel Data (bit weight 64)
P1_A_7	AE14	I ₄	Port 1 A Channel Input Pixel Data (bit weight 32)
P1_A_6	AE13	I ₄	Port 1 A Channel Input Pixel Data (bit weight 16)
P1_A_5	AD13	I ₄	Port 1 A Channel Input Pixel Data (bit weight 8)
P1_A_4	AC13	I ₄	Port 1 A Channel Input Pixel Data (bit weight 4)
P1_A_3	AF14	I ₄	Port 1 A Channel Input Pixel Data (bit weight 2)
P1_A_2	AF13	I ₄	Port 1 A Channel Input Pixel Data (bit weight 1)
P1_A_1	AF12	I ₄	Port 1 A Channel Input Pixel Data (bit weight 0.5)
P1_A_0	AE12	I ₄	Port 1 A Channel Input Pixel Data (bit weight 0.25)
P1_B_9	AF18	I ₄	Port 1 B Channel Input Pixel Data (bit weight 128)
P1_B_8	AB18	I ₄	Port 1 B Channel Input Pixel Data (bit weight 64)
P1_B_7	AC15	I ₄	Port 1 B Channel Input Pixel Data (bit weight 32)
P1_B_6	AC16	I ₄	Port 1 B Channel Input Pixel Data (bit weight 16)
P1_B_5	AD16	I ₄	Port 1 B Channel Input Pixel Data (bit weight 8)
P1_B_4	AE16	I ₄	Port 1 B Channel Input Pixel Data (bit weight 4)
P1_B_3	AF16	I ₄	Port 1 B Channel Input Pixel Data (bit weight 2)
P1_B_2	AF15	I ₄	Port 1 B Channel Input Pixel Data (bit weight 1)
P1_B_1	AC14	I ₄	Port 1 B Channel Input Pixel Data (bit weight 0.5)
P1_B_0	AD14	I ₄	Port 1 B Channel Input Pixel Data (bit weight 0.25)
P1_C_9	AD20	I ₄	Port 1 C Channel Input Pixel Data (bit weight 128)
P1_C_8	AE20	I ₄	Port 1 C Channel Input Pixel Data (bit weight 64)
P1_C_7	AE21	I ₄	Port 1 C Channel Input Pixel Data (bit weight 32)
P1_C_6	AF21	I ₄	Port 1 C Channel Input Pixel Data (bit weight 16)
P1_C_5	AD19	I ₄	Port 1 C Channel Input Pixel Data (bit weight 8)
P1_C_4	AE19	I ₄	Port 1 C Channel Input Pixel Data (bit weight 4)

- (4) Ports 1 and 2 can each be used to support multiple source options for a given product. To do so, the data bus from both source components must be connected to the same port pins (1 or 2) and control given to the DLPC6421 device to tri-state the "inactive" source. Tying them together like this will cause some signal degradation due to reflections on the tri-stated path. Given the clock is the most critical signal, Port clocks (1 and 2) are provided to provide an option to improve the signal integrity.
- (5) Ports 1 and 2 can be combined into one 60-bit port (typically for high data rate sources) for transmission of two pixels per clock.
- (6) The A, B, C input data channels of Ports 1 and 2 can be internally re-configured/ re-mapped for optimum board layout.
- (7) Sources feeding less than the full 10-bits per color component channel should be MSB justified when connected to the DLPC6421 controller and the LSBs tied off to zero. For example an 8-bit per color input should be connected to bits 9:2 of the corresponding A, B, C input channel.

Pin Configurations and Functions (continued)

PIN ⁽¹⁾		I/O ⁽²⁾	DESCRIPTION
NAME	NO.		
P1_C_3	AF19	I ₄	Port 1 C Channel Input Pixel Data (bit weight 2)
P1_C_2	AF20	I ₄	Port 1 C Channel Input Pixel Data (bit weight 1)
P1_C_1	AC19	I ₄	Port 1 C Channel Input Pixel Data (bit weight 0.5)
P1_C_0	AE19	I ₄	Port 1 C Channel Input Pixel Data (bit weight 0.25)
P1_VSYNC	AC20	B ₂	Port 1 Vertical Sync. This signal includes an internal pull-down. While intended to be associated with Port 1, it can be programmed for use with Port 2.
P1_HSYNC	AD21	B ₂	Port 1 Horizontal Sync. This signal includes an internal pull-down. While intended to be associated with Port 1, it can be programmed for use with Port 2.
P2_A_9	AD26	I ₄	Port 2 A Channel Input Pixel Data (bit weight 128)
P2_A_8	AD25	I ₄	Port 2 A Channel Input Pixel Data (bit weight 64)
P2_A_7	AB21	I ₄	Port 2 A Channel Input Pixel Data (bit weight 32)
P2_A_6	AC22	I ₄	Port 2 A Channel Input Pixel Data (bit weight 16)
P2_A_5	AD23	I ₄	Port 1 A Channel Input Pixel Data (bit weight 8)
P2_A_4	AB20	I ₄	Port 2 A Channel Input Pixel Data (bit weight 4)
P2_A_3	AC21	I ₄	Port 2 A Channel Input Pixel Data (bit weight 2)
P2_A_2	AD22	I ₄	Port 2 A Channel Input Pixel Data (bit weight 1)
P2_A_1	AE23	I ₄	Port 2 A Channel Input Pixel Data (bit weight 0.5)
P2_A_0	AB19	I ₄	Port 2 A Channel Input Pixel Data (bit weight 0.25)
P2_B_9	Y22	I ₄	Port 2 B Channel Input Pixel Data (bit weight 128)
P2_B_8	AB26	I ₄	Port 2 B Channel Input Pixel Data (bit weight 64)
P2_B_7	AA23	I ₄	Port 2 B Channel Input Pixel Data (bit weight 32)
P2_B_6	AB25	I ₄	Port 2 B Channel Input Pixel Data (bit weight 16)
P2_B_5	AA22	I ₄	Port 2 B Channel Input Pixel Data (bit weight 8)
P2_B_4	AB24	I ₄	Port 2 B Channel Input Pixel Data (bit weight 4)
P2_B_3	AC26	I ₄	Port 2 B Channel Input Pixel Data (bit weight 2)
P2_B_2	AB23	I ₄	Port 2 B Channel Input Pixel Data (bit weight 1)
P2_B_1	AC25	I ₄	Port 2 B Channel Input Pixel Data (bit weight 0.5)
P2_B_0	AC24	I ₄	Port 2 B Channel Input Pixel Data (bit weight 0.25)
P2_C_9	W23	I ₄	Port 2 C Channel Input Pixel Data (bit weight 128)
P2_C_8	V22	I ₄	Port 2 B Channel Input Pixel Data (bit weight 64)
P2_C_7	Y26	I ₄	Port 2 C Channel Input Pixel Data (bit weight 32)
P2_C_6	Y25	I ₄	Port 2 B Channel Input Pixel Data (bit weight 16)
P2_C_5	Y24	I ₄	Port 2 C Channel Input Pixel Data (bit weight 8)
P2_C_4	Y23	I ₄	Port 2 B Channel Input Pixel Data (bit weight 4)
P2_C_3	W22	I ₄	Port 2 C Channel Input Pixel Data (bit weight 2)
P2_C_2	AA26	I ₄	Port 2 B Channel Input Pixel Data (bit weight 1)
P2_C_1	AA25	I ₄	Port 2 C Channel Input Pixel Data (bit weight 0.5)
P2_C_0	AA24	I ₄	Port 2 B Channel Input Pixel Data (bit weight 0.25)
P2_VSYNC	U22	B ₂	Port 2 Vertical Sync. This signal includes an internal pull-down. While intended to be associated with Port 2, it can be programmed for use with Port1.
P2_HSYNC	W26	B ₂	Port 2 Horizontal Sync. This signal includes an internal pull-down. While intended to be associated with Port 2, it can be programmed for use with Port1.
ALF INPUT PORT CONTROL			
ALF_VSYNC	AF11	I ₄	Reserved
ALF_HSYNC	AD11	I ₄	Reserved
ALF_CSYNC	AE11	I ₄	Reserved
DMD RESET and BIAS CONTROL			
DAD0EZ	AE7	O ₅	Reserved
DADADDR_3	AD6	O ₅	Reserved
DADADDR_2	AE5	O ₅	
DADADDR_1	AF4	O ₅	
DADADDR_0	AB8	O ₅	
DADMODE_1	AD7	O ₅	Reserved
DADMODE_0	AE6	O ₅	
DADSEL_1	AE4	O ₅	Reserved
DADSEL_0	AC7	O ₅	

Pin Configurations and Functions (continued)

PIN ⁽¹⁾		I/O ⁽²⁾	DESCRIPTION
NAME	NO.		
DADSTRB	AF5	O ₅	Reserved
DAD_INTZ	AC8	I ₄	Reserved
DMD LVDS INTERFACE			
DCKA_P	V4	O ₇	DMD, LVDS I/F channel A, differential clock
DCKA_N	V3	O ₇	
SCA_P	V2	O ₇	DMD, LVDS I/F channel A, differential serial control
SCA_N	V1	O ₇	
DDA_P_15	P4	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_15	P3	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_14	P2	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_14	P1	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_13	R4	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_13	R3	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_12	R2	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_12	R1	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_11	T4	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_11	T3	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_10	T2	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_10	T1	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_9	U4	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_9	U3	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_8	U2	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_8	U1	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_7	W4	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_7	W3	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_6	W2	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_6	W1	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_5	Y2	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_5	Y1	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_4	Y4	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_4	Y3	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_3	AA2	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_3	AA1	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_2	AA4	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_2	AA3	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_1	AB2	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_1	AB1	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_P_0	AC2	O ₇	DMD, LVDS I/F channel A, differential serial data
DDA_N_0	AC1	O ₇	DMD, LVDS I/F channel A, differential serial data
DCKB_P	J3	O ₇	DMD, LVDS I/F channel A, differential clock
DCKB_N	J4	O ₇	DMD, LVDS I/F channel A, differential clock
SCB_P	J1	O ₇	DMD, LVDS I/F channel A, differential serial control
SCB_N	J2	O ₇	DMD, LVDS I/F channel A, differential serial control
DDB_P_15	N1	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_15	N2	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_14	N3	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_14	N4	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_13	M2	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_13	M1	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_12	M3	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_12	M4	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_11	L1	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_11	L2	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_10	L3	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_10	L4	O ₇	DMD, LVDS I/F channel B, differential serial data

Pin Configurations and Functions (continued)

PIN ⁽¹⁾		I/O ⁽²⁾	DESCRIPTION
NAME	NO.		
DDB_P_9	K1	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_9	K2	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_8	K3	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_8	K4	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_7	H1	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_7	H2	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_6	H3	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_6	H4	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_5	G1	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_5	G2	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_4	G3	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_4	G4	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_3	F1	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_3	F2	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_2	F3	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_2	F4	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_1	E1	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_1	E2	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_P_0	D1	O ₇	DMD, LVDS I/F channel B, differential serial data
DDB_N_0	D2	O ₇	DMD, LVDS I/F channel B, differential serial data
PROGRAM MEMORY (Flash) INTERFACE			
PM_CSZ_0	D13	O ₅	N/A
PM_CSZ_1	E12	O ₅	Boot Flash Chip Select (active low)
PM_CSZ_2	A13	O ₅	N/A
PM_ADDR_22 (GPIO 36)	A12	B ₅	Address Bit 22 (MSB)
PM_ADDR_21 (GPIO 35)	E11	B ₅	Address Bit 21
PM_ADDR_20	D12	O ₅	Address Bit 20
PM_ADDR_19	C12	O ₅	Address Bit 19
PM_ADDR_18	B11	O ₅	Address Bit 18
PM_ADDR_17	A11	O ₅	Address Bit 17
PM_ADDR_16	D11	O ₅	Address Bit 16
PM_ADDR_15	C11	O ₅	Address Bit 15
PM_ADDR_14	E10	O ₅	Address Bit 14
PM_ADDR_13	D10	O ₅	Address Bit 13
PM_ADDR_12	C10	O ₅	Address Bit 12
PM_ADDR_11	B9	O ₅	Address Bit 11
PM_ADDR_10	A9	O ₅	Address Bit 10
PM_ADDR_9	E9	O ₅	Address Bit 9
PM_ADDR_8	D9	O ₅	Address Bit 8
PM_ADDR_7	C9	O ₅	Address Bit 7
PM_ADDR_6	B8	O ₅	Address Bit 6
PM_ADDR_5	A8	O ₅	Address Bit 5
PM_ADDR_4	D8	O ₅	Address Bit 4
PM_ADDR_3	C8	O ₅	Address Bit 3
PM_ADDR_2	B7	O ₅	Address Bit 2
PM_ADDR_1	A7	O ₅	Address Bit 1
PM_ADDR_0	C7	O ₅	Address Bit 0 (LSB)
PM_WEZ	B12	O ₅	Write Enable (active low)
PM_OEZ	C13	O ₅	Output Enable (active low)
PM_BLSZ_1	B6	O ₅	N/A
PM_BLSZ_0	A6	O ₅	N/A
PM_DATA_15	C17	B ₅	Data Bit (15)
PM_DATA_14	B16	B ₅	Data Bit (14)
PM_DATA_13	A16	B ₅	Data Bit (13)
PM_DATA_12	A15	B ₅	Data Bit (12)

Pin Configurations and Functions (continued)

PIN ⁽¹⁾		I/O ⁽²⁾	DESCRIPTION	
NAME	NO.			
PM_DATA_11	B15	B ₅	Data Bit (11)	
PM_DATA_10	D16	B ₅	Data Bit (10)	
PM_DATA_9	C16	B ₅	Data Bit (9)	
PM_DATA_8	E14	B ₅	Data Bit (8)	
PM_DATA_7	D15	B ₅	Data Bit (7)	
PM_DATA_6	C15	B ₅	Data Bit (6)	
PM_DATA_5	B14	B ₅	Data Bit (5)	
PM_DATA_4	A14	B ₅	Data Bit (4)	
PM_DATA_3	E13	B ₅	Data Bit (3)	
PM_DATA_2	D14	B ₅	Data Bit (2)	
PM_DATA_1	C14	B ₅	Data Bit (1)	
PM_DATA_0	B13	B ₅	Data Bit (0)	
PERIPHERAL INTERFACE				
IIC0_SCL	A10	B ₈	I ² C Bus 0, Clock. This bus support 400 kHz, fast mode operation. This signal requires an external pull-up to 3.3-V. The minimum acceptable pull-up value is 1 k Ω . This input is not 5 V tolerant.	
IIC0_SDA	B10	B ₈	2C Bus 0, Data. This bus support 400 kHz, fast mode operation. This signal requires an external pull-up to 3.3-V. The minimum acceptable pull-up value is 1 k Ω . This input is not 5 V tolerant.	
SSP0_CLK	AD4	B ₅	Synchronous Serial Port 0, clock	
SSP0_RXD	AD5	I ₄	Synchronous Serial Port 0, receive data in	
SSP0_TXD	AB7	O ₅	Synchronous Serial Port 0, transmit data out	
SSP0_CSZ_0	AC5	B ₅	Synchronous Serial Port 0, chip select 0 (active low)	
SSP0_CSZ_1	AB6	B ₅	Synchronous Serial Port 0, chip select 1 (active low)	
SSP0_CSZ_2	AC3	B ₅	Synchronous Serial Port 0, chip select 2 (active low)	
UART0_TXD	AB3	O ₅	UART0 transmit data output	
UART0_RXD	AD1	O ₅	UART0 receive data input	
UART0_RTSZ	AD2	O ₅	UART0 ready to send hardware flow control output (active low)	
UART0_CTSZ	AE2	I ₄	UART0 clear to send hardware flow control input (active low)	
USB_DAT_N	C5	B ₉	USB D- I/O	
USB_DAT_P	D6	B ₉	USB D+ I/O	
PMD_INTZ	AE8	I ₄	This signal requires an external pull-up. Uses hysteresis.	
CW_PWM	AD8	O ₅	Reserved	
CW_INDEX	AF7	O ₅	Reserved	
LMPCTRL	AC9	O ₅	Reserved	
LMPSTAT	AF8	I ₄	Reserved	
GENERAL PURPOSE I/O (GPIO)⁽⁸⁾				
			Software Function 1	Alternate Software Function 2
GPIO_82	E3	B ₅	N/A	N/A
GPIO_81	AB10	B ₂	N/A	N/A
GPIO_80	AD9	B ₂	N/A	N/A
GPIO_79	AE9	B ₂	HEARTBEAT(O)	N/A
GPIO_78	AF9	B ₂	FIELD_3D_LR (I)	N/A
GPIO_77	AB11	B ₂	SAS_INTGTR_EN (O)	N/A
GPIO_76	AC10	B ₂	SAS_CSZ (O)	N/A
GPIO_75	AD10	B ₂	SAS_DO (O)	SENSE_FREQ_IN (I)
GPIO_74	AE10	B ₂	SAS_DI (I)	N/A
GPIO_73	AF10	B ₂	SAS_CLK (O)	N/A
GPIO_72	K24	B ₂	SSP2_DI (I)	N/A
GPIO_71	K23	B ₂	SSP2_CLK (B)	N/A
GPIO_70	K22	B ₂	SSP2_CSZ_1 (B)	N/A
GPIO_69	J26	B ₂	SSP2_CSZ_0 (B)	N/A
GPIO_68	J25	B ₂	SSP2_DO (O)	N/A

(8) GPIO signals must be configured by software for input, output, bidirectional, or open-drain. Some GPIOs have one or more alternate use modes, which are also software configurable. The reset default for all optional GPIOs is as an input signal. However, any alternate function connected to these GPIO pins with the exception of general-purpose clocks and PWM generation, are reset. An external pullup to the 3.3-V supply is required for each signal configured as open-drain. External pullup or pulldown resistors may be required to ensure stable operation before software is able to configure these ports.

Pin Configurations and Functions (continued)

PIN ⁽¹⁾		I/O ⁽²⁾	DESCRIPTION	
NAME	NO.			
GPIO_67	J24	B ₂	N/A	N/A
GPIO_66	J23	B ₂	N/A	N/A
GPIO_65	J22	B ₂	N/A	N/A
GPIO_64	H26	B ₂	N/A	N/A
GPIO_63	H25	B ₂	N/A	N/A
GPIO_62	H24	B ₂	N/A	N/A
GPIO_61	H23	B ₂	N/A	N/A
GPIO_60	H22	B ₂	N/A	N/A
GPIO_59	G26	B ₂	N/A	N/A
GPIO_58	G25	B ₂	LED_SENSE_PULSE (O)	N/A
GPIO_57	F25	B ₂	N/A	N/A
GPIO_56	G24	B ₂	I2C_BUSY (O)	SYSTEM_BUSY (O)
GPIO_55	G23	B ₂	N/A	N/A
GPIO_54	F26	B ₂	N/A	N/A
GPIO_53	E26	B ₂	N/A	N/A
GPIO_52	AB12	B ₂	N/A	N/A
GPIO_51	AC11	B ₂	N/A	N/A
GPIO_50	V23	B ₂	N/A	HBT_CLKOUT (O)
GPIO_49	V24	B ₂	N/A	HBT_DO (O)
GPIO_48	V25	B ₂	N/A	N/A
GPIO_47	V26	B ₂	N/A	N/A
GPIO_46	T22	B ₂	PROJ_ON (I)	N/A
GPIO_45	U23	B ₂	N/A	N/A
GPIO_44	U24	B ₂	N/A	HBT_CLKIN_0 (I)
GPIO_43	U25	B ₂	N/A	HBT_DI_0 (I)
GPIO_42	U26	B ₂	N/A	SSP0_CSZ4 (B)
GPIO_41	R22	B ₂	N/A	DASYNC (I)
GPIO_40	T23	B ₂	N/A	N/A
GPIO_39	F24	B ₂	SW reserved (Boot Hold)	SW reserved (Boot Hold)
GPIO_38	E25	B ₂	SW reserved (USB Enumeration Enable)	SW reserved (USB Enumeration Enable)
GPIO_37	G22	B ₂	N/A	N/A
GPIO_36	A12	B ₂	PM_ADDR_22 (O)	N/A
GPIO_35	E11	B ₂	PM_ADDR_21 (O)	N/A
GPIO_34	F23	B ₂	SSP1_CSZ_1 (B)	N/A
GPIO_33	D26	B ₂	SSP1_CSZ_0 (B)	N/A
GPIO_32	E24	B ₂	SSP1_DO (O)	N/A
GPIO_31	F22	B ₂	SSP1_DI (I)	N/A
GPIO_30	D25	B ₂	SSP1_CLK (B)	N/A
GPIO_29	E23	B ₂	N/A	N/A
GPIO_28	C26	B ₂	N/A	N/A
GPIO_27	AB4	B ₂	SSP0_CSZ3 (B)	N/A
GPIO_26	D24	B ₂	Blue LED enable (O)	N/A
GPIO_25	C25	B ₂	Green LED enable (O)	N/A
GPIO_24	B26	B ₂	Red LED enable (O)	N/A
GPIO_23	E21	B ₂	N/A	N/A
GPIO_22	D22	B ₂	N/A	N/A
GPIO_21	E20	B ₂	N/A	N/A
GPIO_20	C23	B ₂	N/A	N/A
GPIO_19	D21	B ₂	N/A	N/A
GPIO_18	B24	B ₂	N/A	N/A
GPIO_17	C22	B ₂	N/A	N/A
GPIO_16	B23	B ₂	N/A	N/A
GPIO_15	E19	B ₂	I2C_1 SDA (B)	N/A
GPIO_14	D20	B ₂	I2C_1 SCL (B)	N/A

Pin Configurations and Functions (continued)

PIN ⁽¹⁾		I/O ⁽²⁾	DESCRIPTION
NAME	NO.		
GPIO_13	C21	B ₂	N/A I2C_2 SDA (B)
GPIO_12	B22	B ₂	N/A I2C_2 SCL (B)
GPIO_11	A23	B ₂	N/A
GPIO_10	A22	B ₂	N/A
GPIO_9	B21	B ₂	N/A
GPIO_8	A21	B ₂	N/A
GPIO_7	A20	B ₂	N/A
GPIO_6	C20	B ₂	N/A
GPIO_5	B20	B ₂	N/A
GPIO_4	B19	B ₂	N/A
GPIO_3	A19	B ₂	N/A
GPIO_2	E18	B ₂	N/A
GPIO_1	D19	B ₂	N/A
GPIO_0	C19	B ₂	N/A
CLOCK and PLL SUPPORT			
MOSC	M26	I ₁₀	System clock oscillator input (3.3-V LVTTTL). Note that MOSC must be stable a maximum of 25ms after POSENSE transitions from low to high.
MOSCN	N26	O ₁₀	MOSC crystal return
OCLKA	AF6	O ₅	General purpose output clock A.
DUAL CONTROLLER SUPPORT			
SEQ_SYNC	AB9	B ₃	Sequence Sync. This signal is used in multi controller configurations only, in which case the SEQSYNC signal from each controller should be connected together with an external pull-up. This signal should either be pulled high or pulled low and not allowed to float for single controller configurations.
POWER and GROUND			
VDD33	F20, F17, F11, F8, L21, R21, Y21, AA19, AA16, AA10, AA7	POWER	3.3-V I/O Power
VDD18	C1, F5, G6, K6, M5, P5, T5, W6, AA5, AE1, H5, N6, T6, AA13, U21, P21, H21, F14	POWER	1.8-V Internal DRAM & LVDS I/O Power
VDD11	F19, F16, F13, F10, F7, H6, L6, P6, U6, Y6, AA8, AA11, AA14, AA17, AA20, W21, T21, N21, K21, G21, L11, T11, T16, L16	POWER	1.1-V Core Power
VDD_PLLD	L22	POWER	1.1-V DMD clock generator PLL digital power
VSS_PLLD	L23	GROUND	1.1-V DMD clock generator PLL digital ground
VAD_PLLD	K25	POWER	1.8-V DMD clock generator PLL analog power
VAS_PLLD	K26	GROUND	1.8-V DMD clock generator PLL analog ground
VDD_PLLM1	L26	POWER	1.1-V Master-LS clock generator PLL digital power
VSS_PLLM1	M22	GROUND	1.1-V Master-LS clock generator PLL digital ground
VAD_PLLM1	L24	POWER	1.8-V Master-LS clock generator PLL analog power
VAS_PLLM1	L25	GROUND	1.8-V Master-LS clock generator PLL analog ground
VDD_PLLM2	P23	POWER	1.1-V Master-HS clock generator PLL digital power
VSS_PLLM2	P24	GROUND	1.1-V Master-HS clock generator PLL digital ground
VAD_PLLM2	R25	POWER	1.8-V Master-HS clock generator PLL analog power
VAS_PLLM2	R26	GROUND	1.8-V Master-HS clock generator PLL analog ground
VAD_PLLS	R23	POWER	1.1-V video-2X clock generator PLL analog power
VAS_PLLS	R24	GROUND	1.1-V video-2X clock generator PLL analog ground
L-VDQPAD_[7:0], R-VDQPAD_[7:0]	B18, D18, B17, E17, A18, C18, A17, D17, AE17, AC17, AF17, AC18, AB16, AD17, AB17, AD18	RESERVED	These should be tied directly to ground for normal operation.
CFO_VDD33	AE26	RESERVED	This should be tied directly to 3.3 I/O power (VDD33) for normal operation.
VTEST1, VTEST2, VTEST3, VTEST4	AB14, AB15, E15, E16	RESERVED	These should be tied directly to ground for normal operation.
LVDS_AVS1, LVDS_AVS2	V5, K5	POWER	These should be tied directly to ground for normal operation.
VPGM	AC6	POWER	This should be tied directly to ground for normal operation.

Pin Configurations and Functions (continued)

PIN ⁽¹⁾		I/O ⁽²⁾	DESCRIPTION
NAME	NO.		
GROUND	A26, A25, A24, B25, C24, D23, E22, F21, F18, F15, F12, F9, F6, E5, D4, C3, B3, A3, B2, A2, B1, A1 G5, J5, J6, L5, M6, N5, R5, R6, U5, V6, W5, Y5, AA6, AB5, AC4, AD3, AE3, AF3, AF2, AF1, AA9, AA12, AA15, AA18, AA21, AB22, AC23, AD24, AE24, AF24, AE25, AF25, AF26, V21, M21, J21, L15, L14, L13, L12, M16, M15, M14, M13, M12, M11, N16, N15, N14, N13, N12, N11, P16, P15, P14, P13, P12, P11, R16, R15, R14, R13, R12, R11, T15, T14, T13, T12	GROUND	Common ground

Table 1. I/O Type Subscript Definition

SUBSCRIPT	DESCRIPTION	ESD STRUCTURE
2	3.3 LVTTTL I/O Buffer with 8 mA drive	ESD diode to VDD33 and GROUND
3	3.3 LVTTTL I/O Buffer, with 12 mA drive	ESD diode to VDD33 and GROUND
4	3.3 LVTTTL Receiver	ESD diode to VDD33 and GROUND
5	3.3 LVTTTL I/O Buffer with 8 mA drive, with Slew Rate Control	ESD diode to VDD33 and GROUND
6	3.3 LVTTTL I/O Buffer, with programmable 4 mA, 8 mA, or 12 mA drive	ESD diode to VDD33 and GROUND
7	1.8 LVDS (DMD I/F)	ESD diode to VDD33 and GROUND
8	3.3 V I ² C with 3 mA sink	ESD diode to VDD33 and GROUND
9	USB Compatible (3.3 V)	ESD diode to VDD33 and GROUND
10	OSC 3.3 V I/O Compatible LVTTTL	ESD diode to VDD33 and GROUND

6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)⁽¹⁾

Parameter		MIN	MAX	UNIT
ELECTRICAL				
Supply Voltage ⁽²⁾	V _{DD11} (Core)	-0.30	1.60	V
	V _{DD18} (LVDS I/O and Internal DRAM)	-0.30	2.50	
	V _{DD33} (I/O)	-0.30	3.90	
	VDD_PLLD (1.1-V DMD clock generator - Digital)	-0.30	1.60	
	VDD_PLLM1 (1.1-V Master - LS clock generator - Digital)	-0.30	1.60	
	VDD_PLLM2 (1.1-V Master - HS clock generator - Digital)	-0.30	1.60	
	VDD_PLLD (1.8-V DMD clock generator - Analog)	-0.30	2.50	
	VDD_PLLM1 (1.8-V Master - LS clock generator - Analog)	-0.30	2.50	
	VDD_PLLM2 (1.8-V Master - HS clock generator - Analog)	-0.30	2.50	
	VDD_PLLS (1.1-V Video 2X - Analog)	-0.50	1.40	
V _I Input Voltage ⁽³⁾	USB	-1.0	5.25	V
	OSC	-0.3	V _{DD33} + 0.3	
	3.3 LVTTTL	-0.3	3.6	
	3.3 I ² C	-0.5	3.8	
V _O Output Voltage	USB	-1.0	5.25	V
	OSC	-0.3	2.2	
	3.3 LVTTTL	-0.3	3.6	
	3.3 I ² C	-0.5	3.8	
ENVIRONMENTAL				
T _J Operating junction temperature		0	111	°C
T _{stg} Storage temperature range		-40	125	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to GROUND.

(3) Applies to external input and bidirectional buffers.

6.2 ESD Ratings

Parameter		VALUE	UNIT
V _(ESD) Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	± 2000	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	+500/-300	
	Machine Model (MM)	± 200	

(1) Level listed above is the passing level per ANSI, ESDA, and JEDEC JS-001. JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.

(2) Level listed above is the passing level per EIA-JEDEC JESD22-C101. JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

Parameter		I/O ⁽¹⁾	MIN	NOM	MAX	UNIT
ELECTRICAL						
VDD33	3.3-V Supply voltage, I/O		3.135	3.3	3.465	V
VDD18	1.8-V Supply voltage, LVDS & DRAM		1.71	1.8	1.89	V

(1) The number inside each parenthesis for the I/O refers to the type defined in the I/O type subscript definition section.

Recommended Operating Conditions (continued)

Over operating free-air temperature range (unless otherwise noted)

Parameter		I/O ⁽¹⁾	MIN	NOM	MAX	UNIT
VDD11	1.1-V Supply voltage, Core logic		1.045	1.1	1.155	V
VDD_PLLD	1.8-V Supply voltage, PLL Analog		1.71	1.8	1.89	V
VDD_PLLM1	1.8-V Supply voltage, PLL Analog		1.71	1.8	1.89	V
VDD_PLLM2	1.8-V Supply voltage, PLL Analog		1.71	1.8	1.89	V
VDD_PLLS	1.8-V Supply voltage, PLL Analog		1.050	1.10	1.150	V
VDD_PLLD	1.8-V Supply voltage, PLL Analog		1.045	1.1	1.155	V
VDD_PLLM1	1.8-V Supply voltage, PLL Analog		1.045	1.1	1.155	V
VDD_PLLM2	1.8-V Supply voltage, PLL Analog		1.045	1.1	1.155	V
V _I	Input Voltage	USB (9)	0		V _{DD33}	V
		OSC (10)	0		V _{DD33}	
		3.3 V LVTTTL (1, 2, 3, 4)	0		V _{DD33}	
		3.3 V I ² C (8)	0		V _{DD33}	
V _O	Output Voltage	USB (8)	0		V _{DD33}	V
		3.3 V LVTTTL (1, 2, 3, 4)	0		V _{DD33}	
		3.3 V I ² C (8)	0		V _{DD33}	
		1.8 V LVDS (7)	0		V _{DD33}	
T _A	Operating ambient temperature range	See ⁽²⁾⁽³⁾	0		55	°C
T _C	Operating top center case temperature	See ⁽³⁾⁽⁴⁾	0		109.16	°C
T _J	Operating junction temperature		0		111	°C

- (2) Assumes minimum 1 m/s airflow along with the JEDEC thermal resistance and associated conditions listed at www.ti.com/packaging. Thus this is an approximate value that varies with environment and PCB design.
- (3) Maximum thermal values assume max power of 4.6 Watts.
- (4) Assume Ψ_{iJT} equals 0.4 C/W.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		DLPC6421	UNIT
		ZPC (BGA)	
		516 PINS	
R _{θJA}	Junction-to-ambient thermal resistance ⁽²⁾	14.4	°C/W
R _{θJC}	Junction-to-case thermal resistance	4.4	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics Application Report*, SPRA953.
- (2) In still air.

6.5 Electrical Characteristics ⁽¹⁾

Over recommended operating conditions

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IH}	High-level input voltage	USB (9)	2.0			V
		OSC (10)	2.0			
		3.3-V LVTTTL (1,2,3,4)	2.0			
		3.3-V I ² C (8)	2.4		V _{DD33} + 0.5	

- (1) The number inside each parenthesis or the I/O refers to the type defined in Table 1.

Electrical Characteristics⁽¹⁾ (continued)

Over recommended operating conditions

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IL}	Low-level input voltage	USB (9)			0.8	V
		OSC (10)			0.8	
		3.3-V LVTTTL (1,2,3,4)			0.8	
		3.3-V I ² C (8)		-0.5	1.0	
V _{DIS}	Differential Input Voltage	USB (9)		200		mV
V _{ICM}	Differential Cross Point Voltage	USB (9)		0.8	2.5	V
V _{HYS}	Hysteresis (V _{T+} -V _{T-})	USB (9)		200		mV
		3.3-V LVTTTL (1,2,3,4)		400		
		3.3-V I ² C (8)		300	550	
V _{OH}	High-level output voltage	USB (9)		2.8		V
		1.8-V LVDS (7)		1.520		
		3.3-V LVTTTL (1,2,3)	I _{OH} = Max Rated	2.7		
V _{OL}	Low-level output voltage	USB (9)		0.0	0.3	V
		1.8-V LVDS (7)			0.880	
		3.3-V LVTTTL (1,2,3)	I _{OL} = Max Rated		0.4	
		3.3-V I ² C (8)	I _{OL} = 3 mA sink		0.4	
V _{OD}	Output Differential Voltage	1.8-V LVDS (7)		0.065	0.440	V
I _{IH}	High-level input current	USB (9)			200	μA
		OSC (10)		-10.0	10	
		3.3-V LVTTTL (1-4) without Internal Pull Down	V _{IH} = VDD33	-10.0	10	
		3.3-V LVTTTL (1-4) with Internal Pull Down	V _{IH} = VDD33	10.0	200.0	
		3.3-V I ² C (8)	V _{IH} = VDD33		10.0	
I _{IL}	Low-level input current	USB (9)		-10.0	10.0	μA
		OSC (10)		-10.0	10.0	
		3.3-V LVTTTL (1-4) without Internal Pull Down	V _{OH} = VDD33	-10.0	10.0	
		3.3-V LVTTTL (1-4) with Internal Pull Down	V _{OH} = VDD33	-10.0	-200	
		3.3-V I ² C (8)	V _{OH} = VDD33		-10.0	
I _{OH}	High-level output current	USB (9)			-19.1	mA
		1.8-V LVDS (7) (V _{OD} = 300mV)	V _O = 1.4 V	6.5		
		3.3-V LVTTTL (1)	V _O = 2.4 V	-4.0		
		3.3-V LVTTTL (2)	V _O = 2.4 V	-8.0		
		3.3-V LVTTTL (3)	V _O = 2.4 V	-12.0		
I _{OL}	Low-level output current	USB (9)		19.1		mA
		1.8-V LVDS (7) (V _{OD} = 300mV)	V _O = 1.0 V	6.5		
		3.3-V LVTTTL (1)	V _O = 0.4 V	4.0		
		3.3-V LVTTTL (2)	V _O = 0.4 V	8.0		
		3.3-V LVTTTL (3)	V _O = 0.4 V	12.0		
		3.3-V I ² C (8)		3.0		

Electrical Characteristics⁽¹⁾ (continued)

Over recommended operating conditions

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
I_{OZ}	High-Impedance leakage current	USB (9)			–10	pF	
		LVDS (7)			–10		
		3.3-V LVTTTL (1,2,3)			–10		
		3.3-V I ² C (8)			–10		
C_I	Input capacitance	USB (9)			11.84	17.07	pF
		3.3-V LVTTTL (1)			3.75	5.52	
		3.3-V LVTTTL (2)			3.75	5.52	
		3.3-V LVTTTL (4)			3.75	5.52	
		3.3-V I ² C (8)			5.26	6.54	
I_{CC11}	Supply voltage, 1.1-V core power	Normal Mode			1474	mA	
I_{CC18}	Supply voltage, 1.8-V power (LVDS I/O & Internal DRAM)	Normal Mode			1005	mA	
I_{CC33}	Supply voltage, 3.3-V I/O power	Normal Mode			33	mA	
$I_{CC11_PLL D}$	Supply voltage, DMD PLL Digital Power (1.1-V)	Normal Mode		4.4	6.2	mA	
$I_{CC11_PLL M1}$	Supply voltage, Master-LS Clock Generator PLL Digital power (1.1-V)	Normal Mode		4.4	6.2	mA	
$I_{CC11_PLL M2}$	Supply voltage, Master-HS Clock Generator PLL Digital power (1.1-V)	Normal Mode		4.4	6.2	mA	
$I_{CC18_PLL D}$	Supply voltage, DMD PLL Analog Power (1.8 V)	Normal Mode		8.0	10.2	mA	
$I_{CC18_PLL M1}$	Supply voltage, Master-LS Clock Generator PLL Analog power (1.8-V)	Normal Mode		8.0	10.2	mA	
$I_{CC18_PLL M2}$	Supply voltage, Master-HS Clock Generator PLL Analog power (1.8-V)	Normal Mode		8.0	10.2	mA	
$I_{CC11_PLL S}$	Supply voltage, Video-2X PLL Analog Power (1.1-V)	Normal Mode			2.9	mA	
Total Power		Normal Mode			3.73	W	

6.6 System Oscillators Timing Requirements

Over operating free-air temperature range(unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
SYSTEM OSCILLATORS				
f_{clock}	Clock frequency, MOSC ⁽¹⁾	19.998	20.002	MHz
t_c	Cycle time, MOSC ⁽¹⁾	49.995	50.005	MHz
$t_{w(H)}$	Pulse duration ⁽²⁾ , MOSC, high	50% to 50% reference points (signal)	20	ns
$t_{w(L)}$	Pulse duration ⁽²⁾ , MOSC, low	50% to 50% reference points (signal)	20	ns
t_t	Transition time ⁽²⁾ , MOSC, $t_t = t_f/t_r$	20% to 80% reference points (signal)	12	ns
t_{jp}	Period Jitter ⁽²⁾ , MOSC (This is the deviation in period from the ideal period due solely to high frequency jitter).		18	ps

(1) The frequency range for MOSC is 20 MHz with ± 100 PPM accuracy (This shall include impact to accuracy due to aging, temperature and trim sensitivity). The MOSC input can not support spread spectrum clock spreading.

(2) Applies only when driven via an external digital oscillator.

6.7 Test and Reset Timing Requirements

Parameter	TEST CONDITIONS	MIN	MAX	UNIT
$t_{W1(L)}$	Pulse duration, inactive low, PWRGOOD	50% to 50% reference points (signal)	4.0	μ s

Test and Reset Timing Requirements (continued)

Parameter			MIN	MAX	UNIT
$t_{W1(L)}$	Pulse duration, inactive low, PWRGOOD	50% to 50% reference points (signal)		1000 ⁽¹⁾	ms
t_{t1}	Transition time, PWRGOOD, $t_{t1} = t_f/t_r$	20% to 80% reference points (signal)		625	μ s
$t_{W2(L)}$	Pulse duration, inactive low, POSENSE	50% to 50% reference points (signal)	500		μ s
$t_{W2(L)}$	Pulse duration, inactive low, POSENSE	50% to 50% reference points (signal)		1000 ⁽¹⁾	ms
t_{t2}	Transition time, POSENSE, $t_{t1} = t_f/t_r$	20% to 80% reference points (signal)		25 ⁽²⁾	μ s
t_{PH}	Power Hold time, POSENSE remains active after PWRGOOD is de-asserted	20% to 80% reference points (signal)	500		μ s
t_{EW}	Early Warning time, PWRGOOD goes inactive low prior to any power supply voltage going below its specification		500		μ s
$t_{W1(L)} + t_{W2(L)}$	The sum of PWRGOOD and POSENSE inactive time			1050 ⁽¹⁾	ms

(1) With 1.8-V power applied.

(2) As long as noise on this signal is below the hysteresis threshold.

6.8 JTAG Interface: I/O Boundary Scan Application Timing Requirements

Parameter		MIN	MAX	UNIT
f_{clock}	Clock frequency, TCK		10	MHZ
t_{C}	Cycle time, TCK	100		ns
$t_{\text{W(H)}}$	Pulse duration, high 50% to 50% reference points (signal)	40		ns
$t_{\text{W(L)}}$	Pulse duration, low 50% to 50% reference points (signal)	40		ns
t_{t}	Transition time, $t_{\text{t}} = t_{\text{f}}/t_{\text{r}}$ 20% to 80% reference points (signal)		5	ns
t_{SU}	Setup time, TDI valid before TCK↑	8		ns
t_{h}	Hold time, TDI valid after TCK↑	2		ns
t_{SU}	Setup time, TMS1 valid before TCK↑	8		ns
t_{h}	Hold time, TMS1 valid before TCK↑	2		ns

6.9 Port 1 Input Pixel Timing Requirements

Parameter		TEST CONDITIONS	MIN	MAX	UNIT
f_{clock}	Clock frequency, P_CLK1, P_CLK2, P_CLK3 (30-bit bus)		12	175	MHz
f_{clock}	Clock frequency, P_CLK1, P_CLK2, P_CLK3 (60-bit bus)		12	160	MHz
t_{C}	Cycle Time, P_CLK1, P_CLK2, P_CLK3		5.714	83.33	ns
$t_{\text{W(H)}}$	Pulse Duration, high 50% to 50% reference points (signal)		2.3		ns
$t_{\text{W(L)}}$	Pulse Duration, low 50% to 50% reference points (signal)		2.3		ns
t_{jp}	Clock period jitter, P_CLK1, P_CLK2, P_CLK3	Max f_{clock}		See ⁽¹⁾	ps
t_{t}	Transition time, $t_{\text{t}} = t_{\text{f}}/t_{\text{r}}$, P_CLK1, P_CLK2, P_CLK3	20% to 80% reference points (signal)	0.6	2.0	ns
t_{t}	Transition time, $t_{\text{t}} = t_{\text{f}}/t_{\text{r}}$, P1_A(9-0), P1_B(9-0), P1_C(9-0), P1_HSYNC, P1_VSYNC, P1_DATAEN	20% to 80% reference points (signal)	0.6	3.0	ns
t_{t}	Transition time, $t_{\text{t}} = t_{\text{f}}/t_{\text{r}}$, ALF_HSYNC, ALF_VSYNC, ALF_CS _{SYNC} ⁽²⁾	20% to 80% reference points (signal)	0.6	3.0	ns
SETUP AND HOLD TIMES					
t_{SU}	Setup time, P1_A(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{h}	Hold time, P1_A(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{SU}	Setup time, P1_B(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{h}	Hold time, P1_B(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{SU}	Setup time, P1_C(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{h}	Hold time, P1_C(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{SU}	Setup time, P1_VSYNC, valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{h}	Hold time, P1_VSYNC valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{SU}	Setup time, P1_HSYNC, valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{h}	Hold time, P1_HSYNC valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{SU}	Setup time, P2_A(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns

(1) For frequencies (f_{clock}) less than 175 MHZ, use following formula to obtain the jitter: Max Clock Jitter = +/- $[(1/f_{\text{clock}}) - 5414]$ ps

(2) ALF_CS_{SYNC}, ALF_VSYNC and ALF_HSYNC are Asynchronous signals.

Port 1 Input Pixel Timing Requirements (continued)

Parameter		TEST CONDITIONS	MIN	MAX	UNIT
t_h	Hold time, P2_A(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{su}	Setup time, P2_B(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_h	Hold time, P2_B(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{su}	Setup time, P2_C(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_h	Hold time, P2_C(9-0), valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{su}	Setup time, P2_VSYNC, valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_h	Hold time, P2_VSYNC valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{su}	Setup time, P2_HSYNC, valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_h	Hold time, P2_HSYNC valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{su}	Setup time, P_DATAEN1, valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_h	Hold time, P_DATAEN1 valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_{su}	Setup time, P_DATAEN2, valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
t_h	Hold time, P_DATAEN2 valid before P_CLK1↑↓, P_CLK2↑↓, or P_CLK3↑↓		0.8		ns
$t_{w(A)}$	VSYNC Active Pulse Width		1		Video Line
$t_{w(A)}$	HSYNC Active Pulse Width		16		Pixel Clocks

6.10 DMD LVDS Interface Timing Requirements

Parameter		FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
f_{clock}	Clock frequency, DCK_A	N/A	DCK_A	100	400	MHz
t_{C}	Cycle time, DCK_A ⁽¹⁾	N/A	DCK_A	2475.3		ps
$t_{\text{W(H)}}$	Pulse duration, high	N/A	DCK_A	1093		ps
$t_{\text{W(L)}}$	Pulse duration, low	N/A	DCK_A	1093		ps
t_{t}	Transition time, $t_{\text{f}}=t_{\text{r}}/t_{\text{f}}$	N/A	DCK_A	100	400	ps
t_{osu}	Output Setup time at max clock rate ⁽²⁾	DCK_A $\uparrow\downarrow$	SCA, DDA(15:0)	438		ps
t_{oh}	Output hold time at max clock rate ⁽²⁾	DCK_A $\uparrow\downarrow$	SCA, DDA(15:0)	438		ps
f_{clock}	Clock frequency, DCK_B	N/A	DCK_B	100	400	MHz
t_{C}	Cycle time, DCK_B ⁽¹⁾	N/A	DCK_B	2475.3		ps
$t_{\text{W(H)}}$	Pulse duration, high	N/A	DCK_B	1093		ps
$t_{\text{W(L)}}$	Pulse duration, low	N/A	DCK_B	1093		ps
t_{t}	Transition time, $t_{\text{f}}=t_{\text{r}}/t_{\text{f}}$	N/A	DCK_B	100	400	ps
t_{osu}	Output Setup time at max clock rate ⁽²⁾	DCK_B $\uparrow\downarrow$	SCA, DDB(15:0)	438		ps
t_{oh}	Output hold time at max clock rate ⁽²⁾	DCK_B $\uparrow\downarrow$	SCA, DDB(15:0)	438		ps
t_{sk}	Output Skew, Channel A to Channel B	DCK_A \uparrow	DCK_B \uparrow		250	ps

- (1) The minimum cycle time (t_{c}) for DCK_A and DCK_B includes 1.0% spread spectrum modulation. User must verify that DMD can support this rate.
- (2) Output Setup & Hold times for DMD clock frequencies below the maximum can be calculated as follows: $t_{\text{osu}}(f_{\text{clock}}) = t_{\text{osu}}(f_{\text{max}}) + 250000 \cdot (1/f_{\text{clock}} - 1/400)$ & $t_{\text{oh}}(f_{\text{clock}}) = t_{\text{oh}}(f_{\text{max}}) + 250000 \cdot (1/f_{\text{clock}} - 1/400)$ where f_{clock} is in MHz.

6.11 Synchronous Serial Port (SSP) Interface Timing Requirements

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
SSP MASTER					
t_{su}	Setup time, SSPx_DI valid before SSPx_CLK		15		ns
t_{su}	Setup time, SSPx_DI valid before SSPx_CLK		15		ns
t_{h}	Hold time, SSPx_DI valid after SSPx_CLK		0		ns
t_{h}	Hold time, SSPx_DI valid after SSPx_CLK		0		ns
t_{t}	Transition time, SSPx_DI, $t_{\text{f}}=t_{\text{r}}/t_{\text{f}}$	20% to 80% reference points (signal)		1.5	ns
SSP SLAVE					
t_{su}	Setup time, SSPx_DI valid before SSPx_CLK		12		ns
t_{su}	Setup time, SSPx_DI valid before SSPx_CLK		12		ns
t_{h}	Hold time, SSPx_DI valid after SSPx_CLK		12		ns
t_{h}	Hold time, SSPx_DI valid after SSPx_CLK		12		ns
t_{t}	Transition time, SSPx_DI, $t_{\text{f}}=t_{\text{r}}/t_{\text{f}}$	20% to 80% reference points (signal)		1.5	ns

6.12 Programmable Output Clocks Switching Characteristics

Over operating free air temperature range, $C_L(\text{min timing}) = 5 \text{ pF}$, $C_L(\text{max timing}) = 50 \text{ pF}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TO (OUTPUT)	MIN	MAX	UNIT
f_{clock}	Clock frequency, OCLKA ⁽¹⁾		OCLKA	0.787	50	MHz
t_C	Cycle Time, OCLKA		OCLKA	20	1270.6	ns
$t_{W(H)}$	Pulse Duration, high ⁽²⁾	50% to 50% reference points (signal)	OCLKA	$(t_C/2)-2$		ns
$t_{W(L)}$	Pulse Duration, low ⁽²⁾	50% to 50% reference points (signal)	OCLKA	$(t_C/2)-2$		ns
	Jitter OCLKA		OCLKA	350		ps
f_{clock}	Clock frequency, OCLKB ⁽¹⁾		OCLKB	0.787	50	MHz
t_C	Cycle Time, OCLKB		OCLKB	20	1270.6	ns
$t_{W(H)}$	Pulse Duration, high ⁽²⁾	50% to 50% reference points (signal)	OCLKB	$(t_C/2)-2$		ns
$t_{W(L)}$	Pulse Duration, low ⁽²⁾	50% to 50% reference points (signal)	OCLKB	$(t_C/2)-2$		ns
	Jitter OCLKB		OCLKB	350		ps
f_{clock}	Clock frequency, OCLKC ⁽¹⁾		OCLKC	0.787	50	MHz
t_C	Cycle Time, OCLKC ⁽²⁾		OCLKC	20	1270.6	ns
$t_{W(H)}$	Pulse Duration, high	50% to 50% reference points (signal)	OCLKC	$(t_C/2)-2$		ns
$t_{W(L)}$	Pulse Duration, low ⁽²⁾	50% to 50% reference points (signal)	OCLKC	$(t_C/2)-2$		ns
	Jitter OCLKC		OCLKC	350		ps

(1) The frequency of OCLKA thru OCLKC is programmable.

(2) The Duty Cycle of OCLKA thru OCLKC will be within +/- 2 ns of 50%.

6.13 Synchronous Serial Port Interface (SSP) Switching Characteristics

Over operating free-air temperature range, $C_L(\text{min timing}) = 5 \text{ pF}$, $C_L(\text{max timing}) = 50 \text{ pF}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
f_{clock}	Clock Frequency, SSPx_CLK		N/A	SSPx_CLK	73	25000	kHz
t_c	Cycle time, SSPx_CLK		N/A	SSPx_CLK	0.040	13.6	μs
$t_{W(H)}$	Pulse Duration, high	50% to 50% reference points (signal)	N/A	SSPx_CLK	40%		
$t_{W(L)}$	Pulse Duration, low	50% to 50% reference points (signal)	N/A	SSPx_CLK	40%		
SSP Master⁽¹⁾							
t_{pd}	Output Propagation, Clock to Q, SSPx_DO ⁽²⁾		SSPx_CLK↓	SSPx_DO	-5	5	ns
t_{pd}	Output Propagation, Clock to Q, SSPx_DO ⁽²⁾		SSPx_CLK↑	SSPx_DO	-5	5	ns
SSP Slave⁽¹⁾							
t_{pd}	Output Propagation, Clock to Q, SSPx_DO ⁽²⁾		SSPx_CLK↓	SSPx_DO	0	34	ns
t_{pd}	Output Propagation, Clock to Q, SSPx_DO ⁽²⁾		SSPx_CLK↑	SSPx_DO	0	34	ns

(1) The SSP can be used as an SSP Master, or as an SSP Slave. When used as a Master, the SSP can be configured to sample DI with the same internal clock edge used to transmit the next DO. This essentially provides a full cycle rather than a half cycle timing path, allowing operation at higher SPI clock frequencies.

(2) The SSP can be configured into four different operational modes/configurations.

Table 2. SSP Clock Operational Modes

SPI Clocking Mode	SPI Clock Polarity (CPOL)	SPI Clock Phase (CPHA)
0	0	0
1	0	1
2	1	0
3	1	1

6.14 JTAG Interface: I/O Boundary Scan Application Switching Characteristics

Over operating free-air temperature range, C_L(min timing) = 5 pF, C_L(max timing) = 85 pF (unless otherwise noted)

PARAMETER	FROM INPUT	TO OUTPUT	MIN	MAX	UNIT
t _{pd}	Output Propagation, Clock to Q	TCK↓	3	12	ns

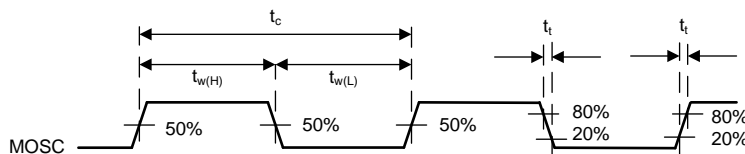
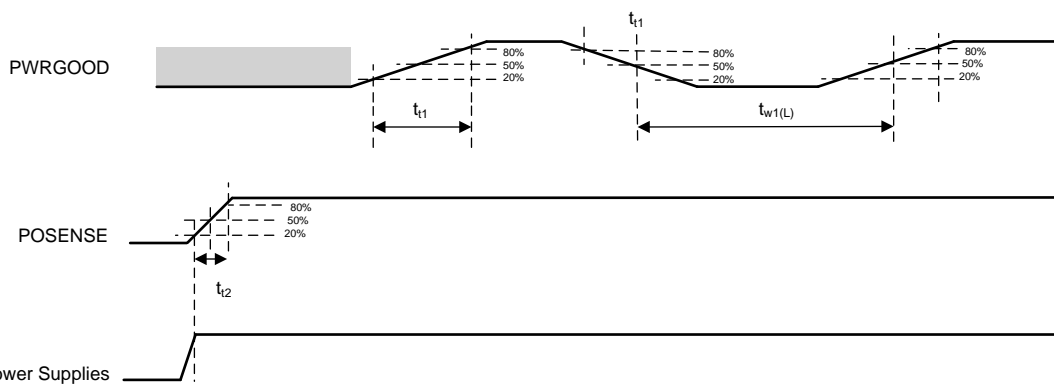


Figure 1. System Oscillators

Power Up



*PWRGOOD has no impact on operation for 60 ms after rising edge of POSENSE.

Figure 2. Power Up

Power Down

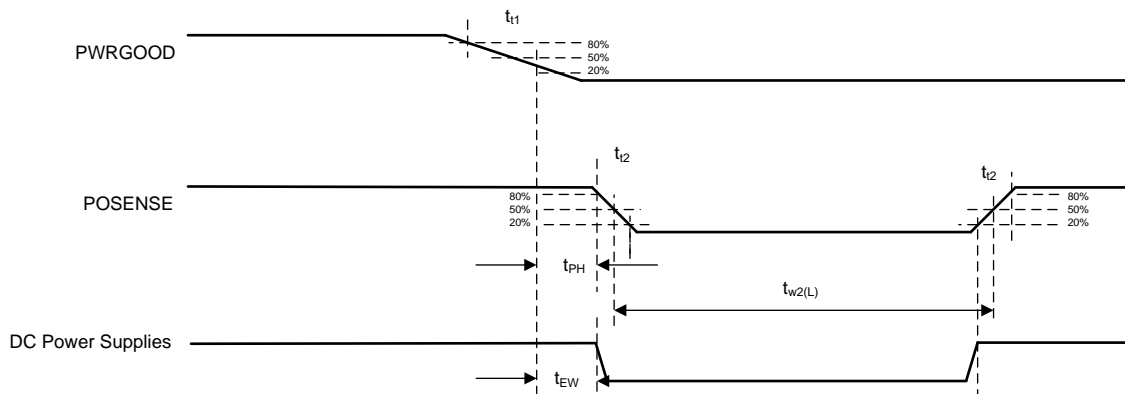
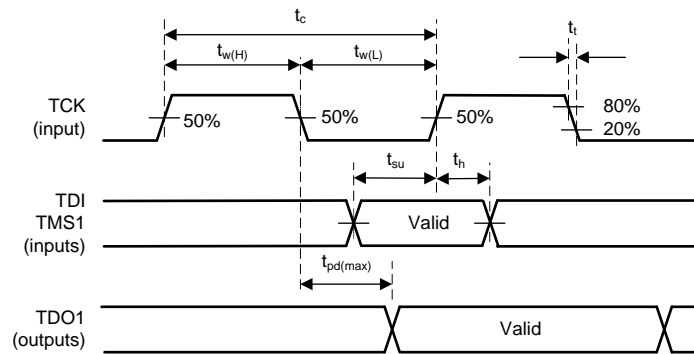
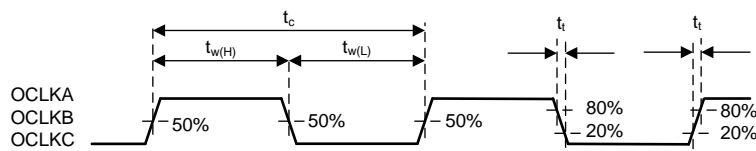
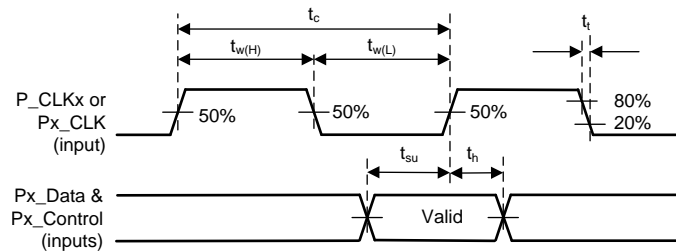
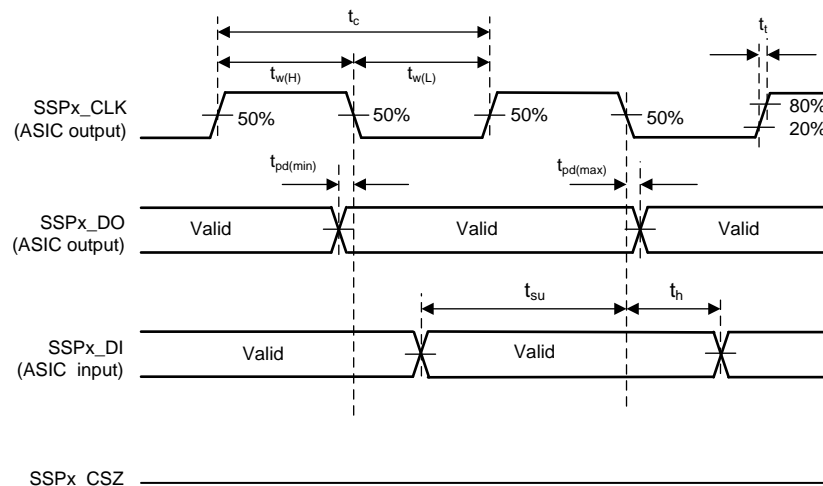


Figure 3. Power Down


Figure 4. I/O Boundary Scan

Figure 5. Programmable Output Clocks

Figure 6. Port1, Port2, and Port3 Input Interface

Figure 7. Synchronous Serial Port Interface - Master

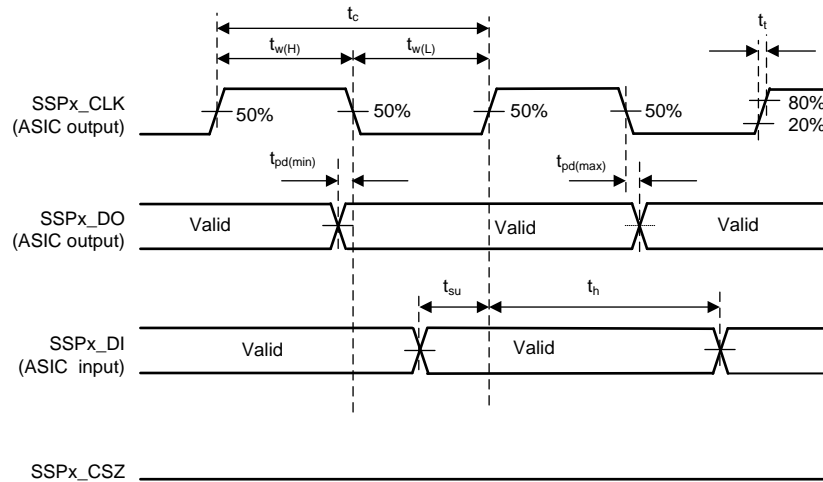


Figure 8. Synchronous Serial Port Interface - Slave

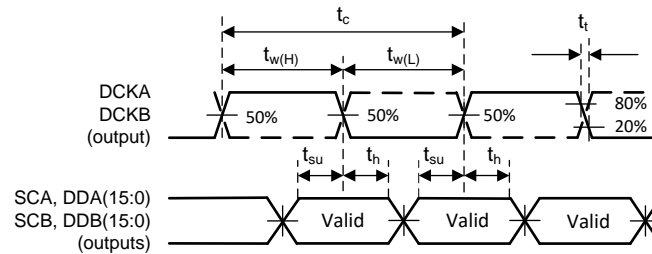


Figure 9. DMD LVDS Interface

7 Detailed Description

7.1 Overview

As with prior DLP® electronics solutions, image data is 100% digital from the DLPC6421 input port to the image projected on to the display screen. The image stays in digital form and is never converted into an analog signal. The DLPC6421 processes the digital input image and converts the data into bit-plane format as needed by the DMD. The DLPC6421 display controller is optimized for high-resolution and high-brightness display applications. Applications include 4K UHD display applications, mobile smart tv, smart home displays, and digital signage.

7.2 Feature Description

7.2.1 System Reset Operation

7.2.1.1 Power-up Reset Operation

Immediately following a power-up event, DLPC6421 hardware automatically brings up the Master PLL and places the DLPC6421 in normal power mode. It then follows the standard system reset procedure (see [System Reset Operation](#)).

7.2.1.2 System Reset Operation

Immediately following any type of system reset (Power-up reset, PWRGOOD reset, watchdog timer timeout, MTR_RSTZ reset, etc), the DLPC6421 device shall automatically return to NORMAL power mode and return to the following state:

- All GPIO will tri-state.
- The Master PLL will remain active (it is reset only after a power-up reset sequence) and most of the derived clocks are active. However, only those resets associated with the ARM9 processor and its peripherals will be released (The ARM9 is responsible for releasing all other resets).
- ARM9 associated clocks default to their full clock rates, boot-up is at full speed.
- All front end derived clocks are disabled.
- The PLL feeding the LVDS DMD I/F (PLLDD) defaults to its power-down mode and all derived clocks are inactive with corresponding resets asserted (The ARM9 is responsible for enabling these clocks and releasing associated resets).
- LVDS I/O defaults to its power-down mode with outputs tri-stated.
- All resets output by the DLPC6421 device remain asserted until released by the ARM9 after boot-up.
- The ARM9 processor boots-up from external flash.

When the ARM9 boots-up, the ARM9 API:

- Configures the programmable DDR Clock Generator (DCG) clock rates (i.e. the DMD LVDS I/F rate)
- Enables the DCG PLL (PLLDD) while holding divider logic in reset
- When the DCG PLL locks, ARM9 software sets DMD clock rates
- API software then releases DCG divider logic resets, which in turn, enable all derived DCG clocks
- Release external resets

Application software then typically waits for a wake-up command through software or through PROJ_ON pin from the end user. When the projector is requested to wake-up, the software places the DLPC6421 back in normal mode, re-initialize clocks, and resets as required.

7.2.2 Spread Spectrum Clock Generator Support

The DLPC6421 controller supports limited, internally-controlled, spread spectrum clock spreading on the DMD interface. The purpose of this is to frequency spread all signals on this high-speed, external interface to reduce EMI emissions. Clock spreading is limited to triangular waveforms. The DLPC6421 controller provides modulation options of 0%, +/-0.5% and +/-1.0% (center-spread modulation).

Feature Description (continued)

7.2.3 GPIO Interface

The DLPC6421 controller provides 83 software-programmable, general-purpose I/O pins. Each GPIO pin is individually configurable as either input or output. In addition, each GPIO output can be either configured as push-pull or open-drain. Some GPIO have one or more alternate-use modes, which are also software configurable. The reset default for all GPIO is as an input signal. However, any alternate function connected to these GPIO pins, with the exception of general purpose clocks and PWM generation, will be reset. When configured as open-drain, the outputs must be externally pulled-up (to the 3.3-V supply). External pull-up or pull-down resistors may be required to ensure stable operation before software is able to configure these ports.

7.2.4 Source Input Blanking

Vertical and horizontal blanking requirements for both input ports are defined as follows (See *Video Timing Parameter Definitions*).

- Minimum port 1 and port 2 vertical blanking
 - Vertical back porch (VBP): 370 μ s
 - Vertical front porch (VFP): 1 line
 - Total vertical blanking (TVB): 370 μ s + 2 lines
- Minimum port1, port 2 horizontal blanking
 - Horizontal back porch (HBP): 10 pixels
 - Horizontal front porch (HFP): 0 pixels
 - Total horizontal blanking (THB): 80 pixels

7.2.5 Video Graphics Processing Delay

The DLPC6421 controller introduces a variable number of frame delays dependent on the source type and selected processing steps performed on the source. For optimum audio/ video synchronization this delay must be matched in the audio path. The following tables define various video delay scenarios to aid in audio matching.

Frame in table refer to source frames.

- For 2-D sources, “N” is defined to be the ratio of the primary channel source frame rate to the display frame rate.
- For 3-D sources, “M” is defined to be the ratio of the primary channel source frame rate required to obtain both the left and right image, to the display frame rate (the rate at which each eye is displayed).

Table 3. Primary Channel/Video-Graphics Processing Delay

Source	Frame Rate Conversion	FRC Type	Formatter Buffer	Total Delay
48 Hz Graphics	1 Frame	Sync (1:1)	N Frames	1 + N Frames
50 Hz Graphics	1 Frame	Sync (1:1)	N Frames	1 + N Frames
60 Hz Graphics	1 Frame	Sync (1:1)	N Frames	1 + N Frames
100 & 120 Hz Graphics	1 Frame	Sync (1:1)	N Frames	1 + N Frames
100 & 120 Hz Graphics (3D)	1 Frame	Sync (1:2)	M Frames	1 + M Frames
240 Hz Graphics	1 Frame	Sync (1:1)	N Frames	1 + N Frames

7.2.6 Program Memory Flash

The DLPC6421 controller provides an external program memory chip select:

- PM_CSZ_1 – dedicated CS for boot flash device (i.e. Standard NOR-type flash, ≤ 128 Mb)

The DLPC6421 controller provides enough Program Memory Address pins to support a flash device up to 128 Mb. The two most significant address bits (i.e. PM_ADDR_22 and PM_ADDR_21) are shared on pins GPIO_36 and GPIO_35 respectively. Like other GPIO pins, these pins float in a high-impedance input state following reset; therefore, if these GPIO pins are to be reconfigured as Program Memory Address pins, they require board-level pull-down resistors to prevent any flash address bits from floating until software is able to reconfigure the pins from GPIO to Program Memory Address. Also note that until software reconfigures the pins from GPIO to Program Memory Address, upper portions of flash memory are not accessible.

Table 4 shows typical GPIO_35 and GPIO36 pin configuration for various flash sizes.

Table 4. Typical GPIO_35 and GPIO_36 Pin Configurations for Various Flash Sizes

FLASH SIZE	GPIO_36 Pin Configuration	GPIO_35 Pin Configuration
32 Mb or less	PM_ADDR_22 ⁽¹⁾	PM_ADDR_21 ⁽¹⁾
64 Mb		
128 Mb		

(1) Board-level pulldown resistor required.

7.2.7 Calibration and Debug Support

The DLPC6421 controller contains a test point output port, TSTPT_(7:0), which provides selected system calibration support as well as debug support. These test points are inputs while reset is applied and switch to outputs when reset is released. The state of these signals is sampled upon the release of system reset and the captured value configures the test mode until the next time reset is applied. Each test point includes an internal pull-down resistor and thus external pull-ups are used to modify the default test configuration. The default configuration (x00) corresponds to the TSTPT_(7:0) outputs being driven low for reduce switching activity during normal operation. For maximum flexibility, an option to jumper to an external pull-up is recommended for TSTPT_(3:0). Note that adding pull-up to TSTPT_(7:4) may have adverse affects for normal operation and are not recommended. Note that these external pull-ups are only sampled upon a zero to one transition on POSENSE and thus changing their configuration after reset has been released will not have any effect until the next time reset is asserted and released. Table 5 defines the test mode selection for 3 of the 16 programmable scenarios defined by TSTPT_(3:0), if a test mode is not selected the system will output the default configuration listed under Default Software Configuration.

Table 5. Test Mode Selection

	No Switching Activity	System Calibration	ARM Debug Signal Set	Default Software Configuration
TSTPT(3:0) Capture Value	x0	x8	x1	N/A
TSTPT(0)	0	Vertical Sync	ARM9_Debug (0)	User Configurable (Default: VSYNC)
TSTPT(1)	0	Delayed CW Index	ARM9_Debug (1)	User Configurable
TSTPT(2)	0	Sequence Index	ARM9_Debug (2)	User Configurable
TSTPT(3)	0	CW Spoke Test Pt	ARM9_Debug (3)	User Configurable (Default: Sequence index)
TSTPT(4)	0	CW Revolution Test Pt	ARM9_Debug (4)	User Configurable
TSTPT(5)	0	Reset Seq. Aux Bit 0	ARM9_Debug (5)	User Configurable
TSTPT(6)	0	Reset Seq. Aux Bit 1	ARM9_Debug (6)	Reserved
TSTPT(7)	0	Reset Seq. Aux Bit 2	ARM9_Debug (7)	User Configurable

7.2.8 Board Level Test Support

The in-circuit tri-state enable signal (ICTSEN) is a board level test control signal. By driving ICTSEN to a logic high state, all DLPC6421 outputs (except TDO1 and TDO2) will be tri-stated.

The DLPC6421 controller also provides JTAG boundary scan support on all I/O except non-digital I/O and a few special signals. [Table 6](#) defines these exceptions.

Table 6. DLPC6421-Signals Not Covered by JTAG

Signal Name	PKG Ball
HW_TEST_EN	M25
MOSC	M26
MOSCN	N26
USB_DAT_N	C5
USB_DAT_P	D6
TCK	N24
TDI	N25
TRSTZ	M23
TDO1	N23
TDO2	N22
TMS1	P25
TMS2	P26

8 Application and Implementation

NOTE

Information in the following applications sections are not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The DLPC6421 display controller is part of the DLP470TP chipset. The controller integrates all system image processing and control and DMD data formatting onto a single integrated circuit (IC). It will support LED or Hybrid illumination systems, and it also includes multiple image processing algorithms such as DynamicBlack™ or BrilliantColor™. Applications of interest include 4K UHD display applications, Mobile smart TV, digital signage and commercial gaming.

8.2 Typical Application

The DLPC6421 controller is ideal for applications requiring high brightness and high resolution displays. When two DLPC6421 display controllers are combined with the DLP470TP DMD, an FPGA, a LED power management device (DLPA3000/DLPA3005), and other electrical, optical and mechanical components, the chipset enables bright, affordable, full 4K UHD display solutions. A typical 4K UHD system application using the two DLPC6421 controllers and DLP470TP DMD is shown in Figure 10, Figure 11.

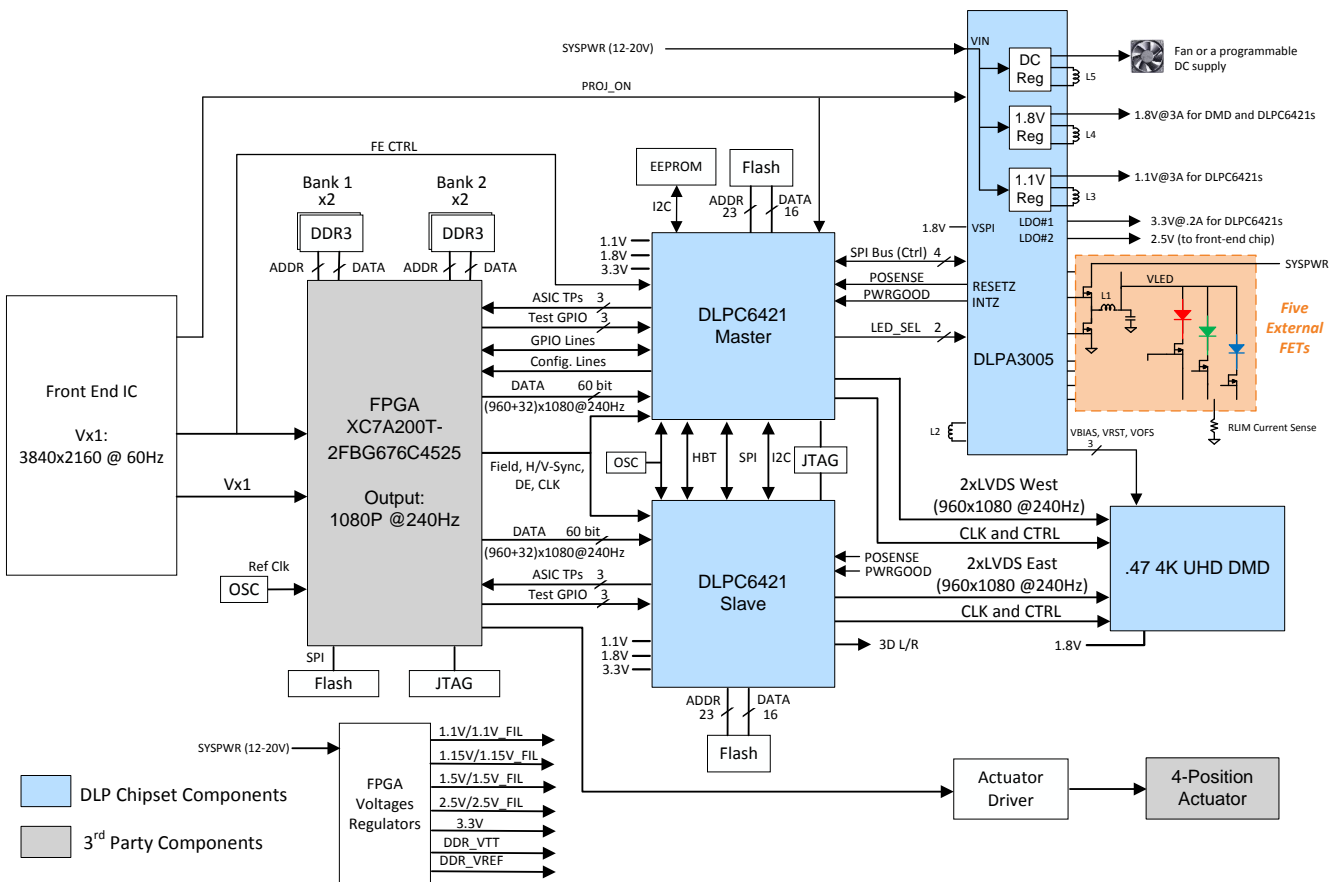


Figure 10. Typical 4K UHD DLPA3005 Display Application

Typical Application (continued)

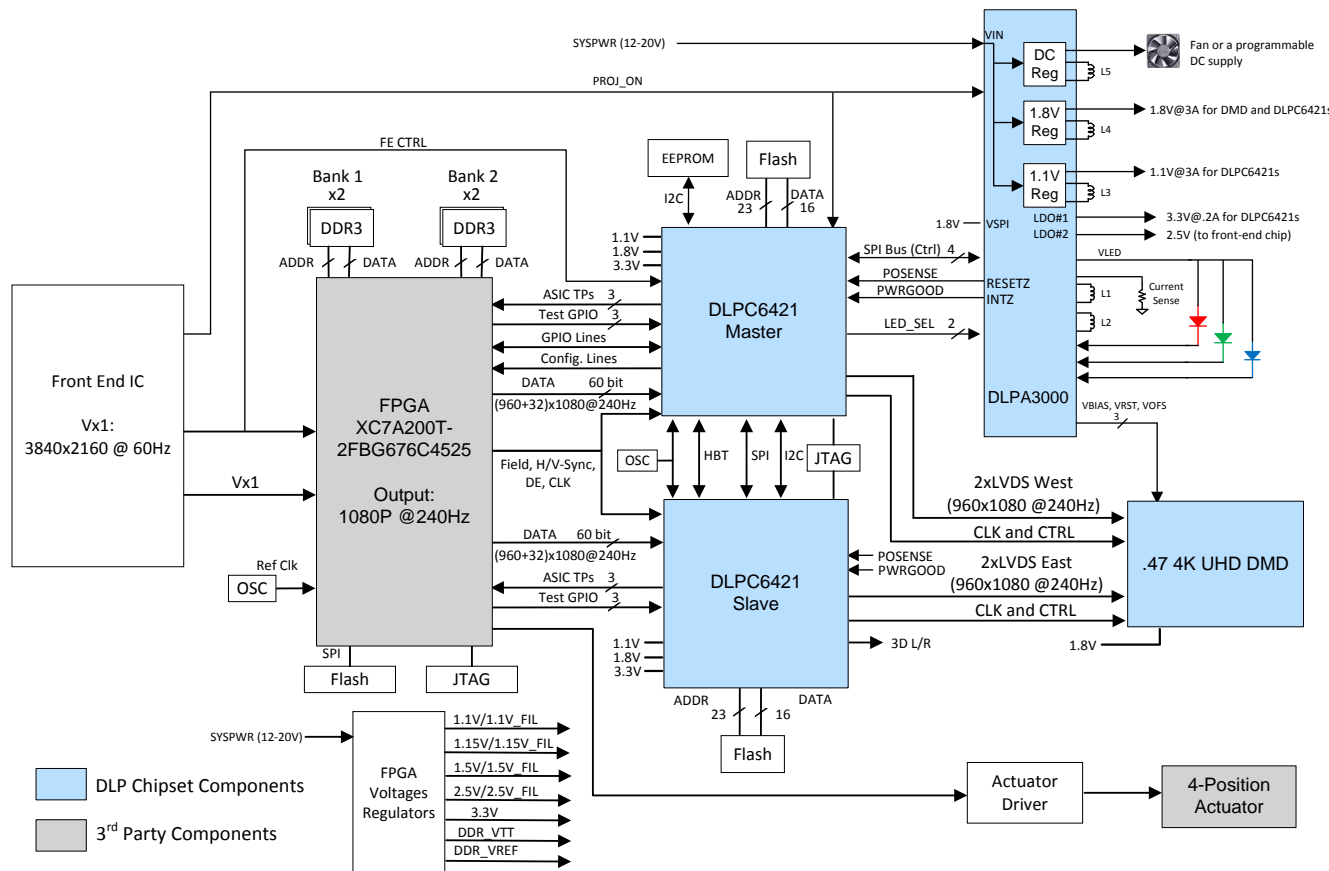


Figure 11. Typical 4K UHD DLPA3000 Display Application

8.2.1 Design Requirements

The display controller is the digital interface between the DMD and the rest of the system. The display controller takes digital input from front end digital receivers and drives the DMD over a high speed interface. The display controller also generates the necessary signals (data, protocols, timings) required to display images on the DMD. Some systems require a dual controller to format the incoming data before sending it to the DMD. Reliable operation of the DMD is only insured when the DMD and the controller are used together in a system. In addition to the DLP devices in the chipset, other devices may be needed. Typically a Flash part is needed to store the software and firmware.

8.2.1.1 Recommended MOSC Crystal Oscillator Configuration

Table 7. Crystal Port Characteristics

PARAMETER	NOMINAL	UNIT
MOSC TO GROUND Capacitance	1.5	pF
MOSCZ TO GROUND Capacitance	1.5	pF

Table 8. Recommended Crystal Configuration

PARAMETER	RECOMMENDED	UNIT
Crystal circuit configuration	Parallel resonant	
Crystal type	Fundamental (1st Harmonic)	
Crystal nominal frequency	20	MHz

Table 8. Recommended Crystal Configuration (continued)

PARAMETER	RECOMMENDED	UNIT
Crystal frequency temperature stability	+/- 30	PPM
Overall crystal frequency tolerance (including accuracy, stability, aging, and trim sensitivity)	+/- 100	PPM
Crystal Equivalent Series Resistor (ESR)	50 max	Ω
Crystal load	20	pF
Crystal shunt load	7 max	pF
RS drive resistor (nominal)	100	Ω
RFB feedback resistor (nominal)	1	M Ω
CL1 external crystal load capacitor (MOSC)	See ⁽¹⁾	pF
CL2 external crystal load capacitor (MOSCN)	See ⁽¹⁾	pF
PCB layout	TI recommends a ground isolation ring around the crystal oscillator.	

(1) Typical drive level with the XSA020000FK1H-OCX Crystal (ESRmax = 40 Ω) = 50 μ W.

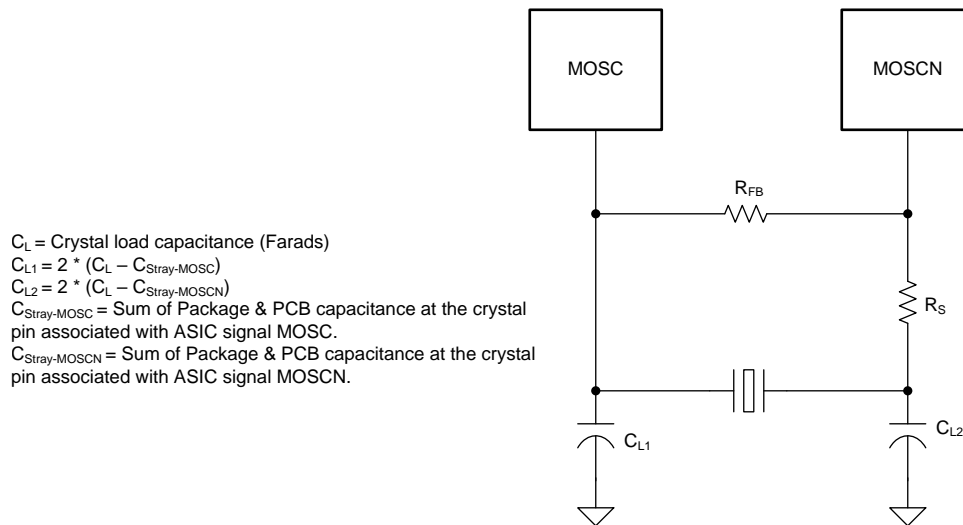


Figure 12. Recommended Crystal Oscillator Configuration

It is assumed that the external crystal oscillator will stabilize within 50 ms after stable power is applied.

8.2.2 Detailed Design Procedure

For connecting the DLPC6421 controller and the DLP470TP DMD together, see the reference design schematic. Layout guidelines should be followed to achieve a reliable projector. To complete the DLP system, an optical module or light engine is required that contains the DLP470TP DMD, associated illumination sources, optical elements, and necessary mechanical components.

8.2.3 General Handling Guidelines for Unused CMOS-type Pins

To avoid potentially damaging current caused by floating CMOS input-only pins, it is recommended that unused ASIC input pins be tied through a pull-up resistor to its associated power supply or a pull-down to ground. For DLPC6421 inputs with an internal pull-up or pull-down resistors, it is unnecessary to add an external pull-up/ pull down unless specifically recommended. Note that internal pull-up & pull-down resistors are weak and should not be expected to drive the external line.

Unused output-only pins can be left open. When possible, it is recommended that unused Bi-directional I/O pins be configured to their output state such that the pin can be left open. If this control is not available and the pins may become an input, then they should be pulled-up (or down) using an appropriate resistor

9 Power Supply Recommendations

9.1 System Power Regulations

TI strongly recommends that the VDD18_PLLD, VDD18_PLLM1, and VDD18_PLLM2 power feeding internal PLLs be derived from an isolated linear regulator in order to minimize the AC noise component. It is acceptable for VDD11_PLLD, VDD11_PLLM1, VDD11_PLLM2, and VDD11_PLLS to be derived from the same regulator as the core VDD11, but they should be filtered.

9.2 System Power-Up Sequence

Although the DLPC6421 controller requires an array of power supply voltages (1.1 V, 1.8 V, 3.3 V), there are no restrictions regarding the relative order of power supply sequencing. This is true for both power-up and power-down scenarios. Similarly, there is no minimum time between powering-up or powering-down the different supplies feeding the DLPC6421 controller. However, note that it is not uncommon for there to be power sequencing requirements for the devices that share the supplies with the DLPC6421 controller.

- 1.1-V core power should be applied whenever any I/O power is applied. This ensures the state of the associated I/O that are powered are controlled to a known state. Thus, TI recommends applying core power first. Other supplies should be applied only after the 1.1-V core has ramped up.
- All DLPC6421 device power should be applied before POSENSE is asserted to ensure proper power-up initialization is performed.

It is assumed that all DLPC6421 device power-up sequencing is handled by external hardware. It is also assumed that an external power monitor will hold the DLPC6421 device in system reset during power-up (i.e. POSENSE = 0). During this time all DLPC6421 device I/O will be tri-stated. The master PLL (PLL1) is released from reset upon the low to high transition of POSENSE but the DLPC6421 device keeps the rest of the device in reset for an additional 60 ms to allow the PLL to lock and stabilize its outputs. After this 60 ms delay the ARM-9 related internal resets will be de-asserted causing the microprocessor to begin its boot-up routine. PROJ_ON is used to trigger the final step of the boot up routine, polling of GPIO_56 (I2C_BUSY/SYSTEM_BUSY) can be used by the front end to determine when to assert PROJ_ON.

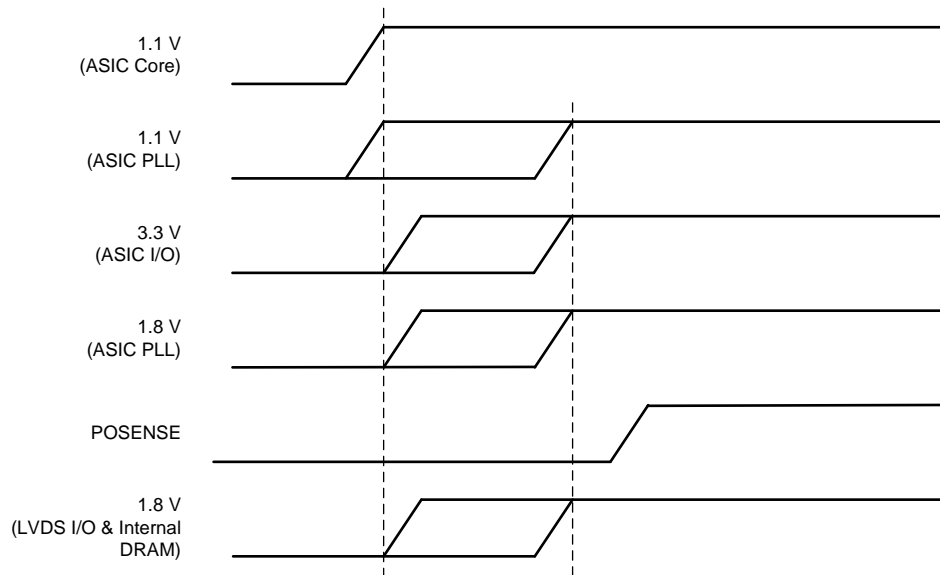


Figure 13. System Power-Up Sequence

9.3 Power-On Sense (POSENSE) Support

It is difficult to set up a power monitor to trip exactly on the DLPC6421 device minimum supply voltage spec. Thus for practical reasons, TI recommends that the external power monitor generating POSENSE target its threshold to 90% of the minimum supply voltage specs and ensure that POSENSE remain low a sufficient amount of time for all supply voltages to reach minimum device requirements and stabilize. Note that the trip voltage for detecting the loss of power, as well as the reaction time to respond to a low voltage condition is not critical for POSENSE as PWRGOOD is used for this purpose. As such, PWRGOOD has critical requirements in these areas.

9.4 System Environment and Defaults

9.4.1 DLPC6421 System Power-Up and Reset Default Conditions

Following system power-up, the DLPC6421 device performs a power-up initialization routine that defaults the device to its normal power mode, in which ARM9-related clocks are enabled at their full rate and associated resets are released. Most other clocks default to disabled state with associated resets asserted until released by the processor. In addition, the default for system power gating enables all power. These same defaults are also applied as part of all system reset events (Watch Dog timer timeout, reset, etc) that occur without removing or cycling power, with the possible exception of power for the LVDS I/O and internal DRAM.

Following power-up or system reset initialization, the ARM9 boots from an external flash memory after which it enables the rest of the DLPC6421 clocks, and initializes the internal DRAM.

9.4.2 1.1-V System Power

The DLPC6421 device can support a low cost power delivery system with a single 1.1-V power source derived from a switching regulator. To enable this approach, appropriate filtering must be provided for the 1.1-V power pins of the PLLs.

9.4.3 1.8-V System Power

TI recommends that the DLPC6421 device power delivery system provide two independent 1.8-V power sources. One of the 1.8-V power sources should be used to supply 1.8-V power to the DLPC6421 device LVDS I/O and internal DRAM. Power for these functions should always be fed from a common source which is recommended to be linear regulator. The second 1.8-V power source should be used (along with appropriate filtering as discussed in the PCB layout guidelines for internal DLPC6421 PLL power section of this document) to supply all of the DLPC6421 device internal PLLs. In order to keep this power as clean as possible, TI highly recommends a dedicated linear regulator for the 1.8-V power to the PLLs.

9.4.4 3.3-V System Power

The DLPC6421 device can support a low cost power delivery system with a single 3.3-V power sources derived from a switching regulator. This 3.3-V power will supply all LVTTTL I/O and the Crystal Oscillator cell. 3.3-V power should remain active in all power modes for which 1.1-V core power is applied.

9.4.5 Power Good (PWRGOOD) Support

The PWRGOOD signal is defined as an early warning signal that alerts the DLPC6421 device a specified amount of time before the DC supply voltages drop below specifications. This allows the DLPC6421 device to park the DMD and to place the system into reset, ensuring the integrity of future operation. For practical reasons, TI recommends that the monitor sensing PWRGOOD be on the input side of supply regulators.

9.4.6 I²C BUSY (I2C_BUSY)

The I2C_BUSY signal indicates when the system is ready to accept incoming commands from the front end, polling is recommended to ensure all I²C transactions are accepted and processed.

9.4.7 5V Tolerant Support

With the exception of USB_DAT, the DLPC6421 device does not support any other 5V tolerant I/O.

10 Layout

10.1 Layout Guidelines

TI recommends 2-ounce copper planes in the PCB design to achieve needed thermal connectivity.

10.1.1 PCB Layout Guidelines for Internal DLPC6421 Power

TI recommends the following guidelines to achieve desired DLPC6421 performance relative to internal PLLs:

- The DLPC6421 device contains four PLLs (PLLM1, PLLM2, PLLD & PLLS), each of which have a dedicated 1.1-V digital supply, and three (PLLM1, PLLM2 & PLLD) which have a dedicated 1.8-V analog supply. It is important to have filtering on the supply pins that covers a broad frequency range. Each 1.1-V PLL supply pin should have individual high frequency filtering in the form of a ferrite bead and a 0.1 μ F ceramic capacitor. These components should be located very close to the individual PLL supply balls. The impedance of the ferrite bead should be much greater than that of the capacitor at frequencies above 10 MHz. The 1.1-V to the PLL supply pins should also have low frequency filtering in the form of an RC filter. This filter can be common to all the PLLs. The voltage drop across the resistor is limited by the 1.1-V regulator tolerance and the DLPC6421 device voltage tolerance. A resistance of 0.36 Ω and a 100 μ F ceramic are recommended.
- The analog 1.8-V PLL power pins should have a similar filter topology as the 1.1-V. In addition, TI recommends that the 1.8-V be generated with a dedicated linear regulator.
- When designing the overall supply filter network, care must be taken to ensure no resonance occurs. Particular care must be taken around the 1- to 2-MHz band, as this coincides with the PLL natural loop frequency.

Layout Guidelines (continued)

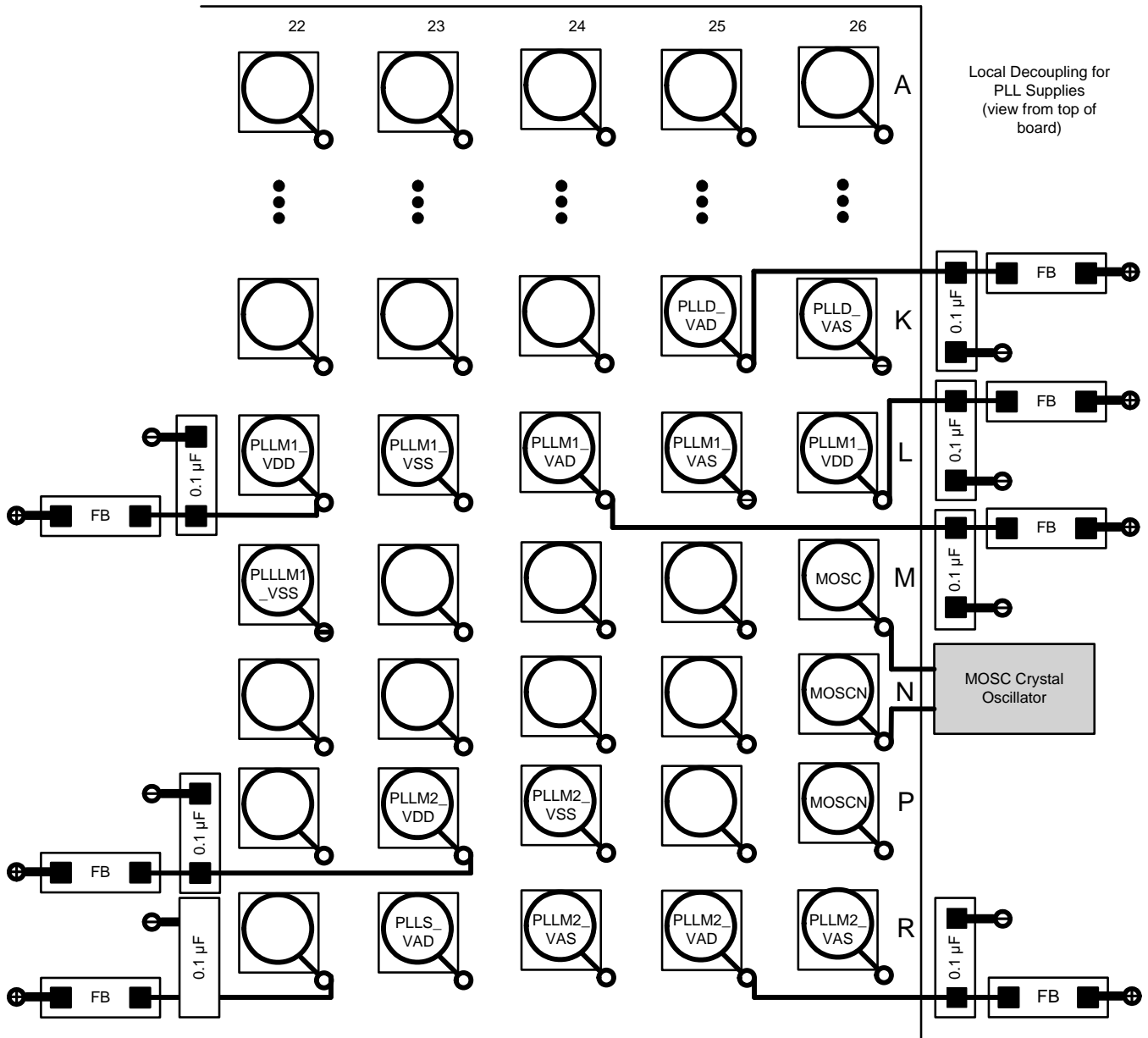
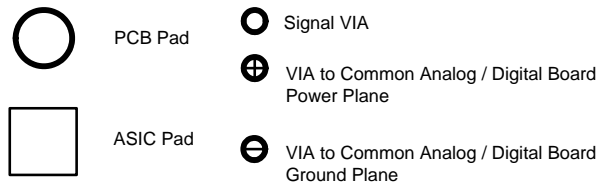


Figure 14. PLL Filter Layout

Layout Guidelines (continued)

High frequency decoupling is required for both 1.1-V and 1.8-V PLL supplies and should be provided as close as possible to each of the PLL supply package pins. TI recommends placing decoupling capacitors under the package on the opposite side of the board. Use high quality, low-ESR, monolithic, surface mount capacitors. Typically 0.1 μ F for each PLL supply should be sufficient. The length of a connecting trace increases the parasitic inductance of the mounting and thus, where possible, there should be no trace, allowing the via to butt up against the land itself. Additionally, the connecting trace should be made as wide as possible. Further improvement can be made by placing vias to the side of the capacitor lands or doubling the number of vias.

The location of bulk decoupling depends on the system design.

10.1.2 DMD Interface Considerations

High speed interface waveform quality and timing on the DLPC6421 device (i.e. the LVDS DMD interface) is dependent on the total length of the interconnect system, the spacing between traces, the characteristic impedance, etch losses, and how well matched the lengths are across the interface. Thus ensuring positive timing margin requires attention to many factors.

As an example, DMD Interface system timing margin can be calculated as follows:

- Setup Margin = (DLPC6421 output setup) – (DMD input setup) – (PCB routing mismatch) – (PCB SI degradation)
- Hold-time Margin = (DLPC6421 output hold) – (DMD input hold) – (PCB routing mismatch) – (PCB SI degradation)

Where *PCB SI degradation* is signal integrity degradation due to PCB effects, which include simultaneously switching output (SSO) noise, cross-talk and inter-symbol interference (ISI) noise. The DLPC6421 device I/O timing parameters as well as DMD I/O timing parameters can be easily found in their corresponding datasheets. Similarly, *PCB routing mismatch* can be budgeted and met through controlled PCB routing. However, PCB SI degradation is not so straight forward.

In an attempt to minimize the signal integrity analysis that would otherwise be required, the following PCB design guidelines are provided as a reference of an interconnect system that satisfies both waveform quality and timing requirements (accounting for both PCB routing mismatch and PCB SI degradation). Variation from these recommendations may also work, but should be confirmed with PCB signal integrity analysis or lab measurements

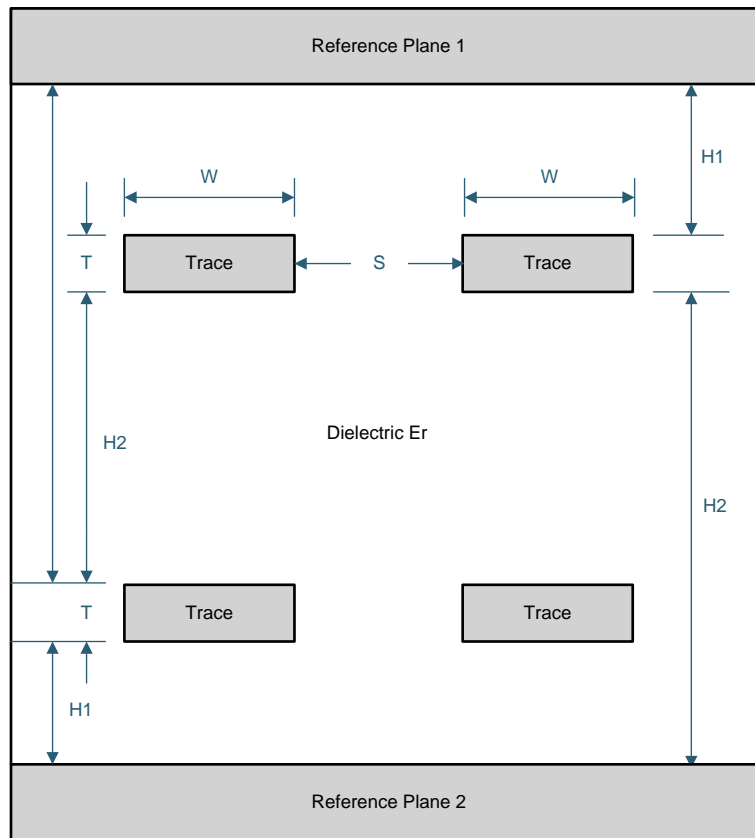
PDB Design:

- | | |
|---------------------------------|---------------------------------|
| • Configuration | Asymmetric Dual Stripline |
| • Etch Thickness | 1.0 oz copper (1.2 mil) |
| • Flex Etch Thickness | 0.5 oz copper (0.6 mil) |
| • Single Ended Signal Impedance | 50 ohms (+/- 10%) |
| • Differential Signal Impedance | 100 ohms differential (+/- 10%) |

PCB Stackup:

- Reference plane 1 is assumed to be a ground plane for proper return path
- Reference plane 2 is assumed to be the I/O power plane or ground
- Dielectric FR4, (Er): 4.2 (nominal)
- Signal trace distance to reference plane 1 (H1) 5.0 mil (nominal)
- Signal trace distance to reference plane 2 (H2) 34.2 mil (nominal)

Layout Guidelines (continued)



PCB Stackup Geometries

Figure 15. PCB Stackup Geometries

Layout Guidelines (continued)
Table 9. General PCB Routing (Applies to All Corresponding PCB Signals)

PARAMETER	APPLICATION	SINGLE-ENDED SIGNAL	DIFFERENTIAL PAIRS	UNIT
Line width (W) ⁽¹⁾	Escape Routing in Ball Field	4 (0.1)	4 (0.1)	mil (mm)
	PCB Etch Data or Control	7 (0.18)	4.25 (0.11)	mil (mm)
	PCB Etch Clocks	7 (0.18)	4.25 (0.11)	mil (mm)
Minimum Line spacing to other signals (S)	Escape Routing in Ball Field	4 (0.1)	4 (0.1)	mil (mm)
	PCB Etch Data or Control	10 (0.25)	20 (0.51)	mil (mm)
	PCB Etch Clocks	20 (0.51)	20 (0.51)	mil (mm)

(1) Line width is expected to be adjusted to achieve impedance requirements

Table 10. DMD I/F, PCB Interconnect Length Matching Requirements⁽¹⁾⁽²⁾

SIGNAL GROUP LENGTH MATCHING				
I/F	SIGNAL GROUP	REFERENCE SIGNAL	MAX MISMATCH	UNIT
DMD (LVDS)	SCA_P, SCA_N, DDA_P(15:0), DDA_N(15:0)	DCKA_P, DCKA_N	+/-150 (+/-3.81)	mil (mm)
DMD (LVDS)	SCB_P, SCB_N, DDB_P(15:0), DDB_N(15:0)	DCKB_P, DCKB_N	+/-150 (+/-3.81)	mil (mm)

(1) These values apply to the PCB routing only. They do not include any internal package routing mismatch associated with the DLPC6421 controller or the DMD. Additional margin can be attained if internal DLPC6421 package skew is taken into account.

(2) To minimize EMI radiation, serpentine routes added to facilitate matching should be implemented on signal layers only, and between reference planes.

Number of layer changes:

- Single ended signals: Minimize
- Differential signals: Individual differential pairs can be routed on different layers but the signals of a given pair should not change layers.

Termination requirements:

- DMD Interface: None, the DMD receiver is differentially terminated to 100 ohm internally
Connector (DMD-LVDS I/F bus only) - High Speed Connectors that meet the following requirements should be used:

- Differential Crosstalk <5 %
- Differential Impedance 75-125 ohms

Routing requirements for right angle connectors:

When using right angle connectors, P-N pairs should be routed in same row to minimize delay mismatch.

When using right angle connectors, propagation delay difference for each row should be accounted for on associated PCB etch lengths.

10.1.3 Layout Example

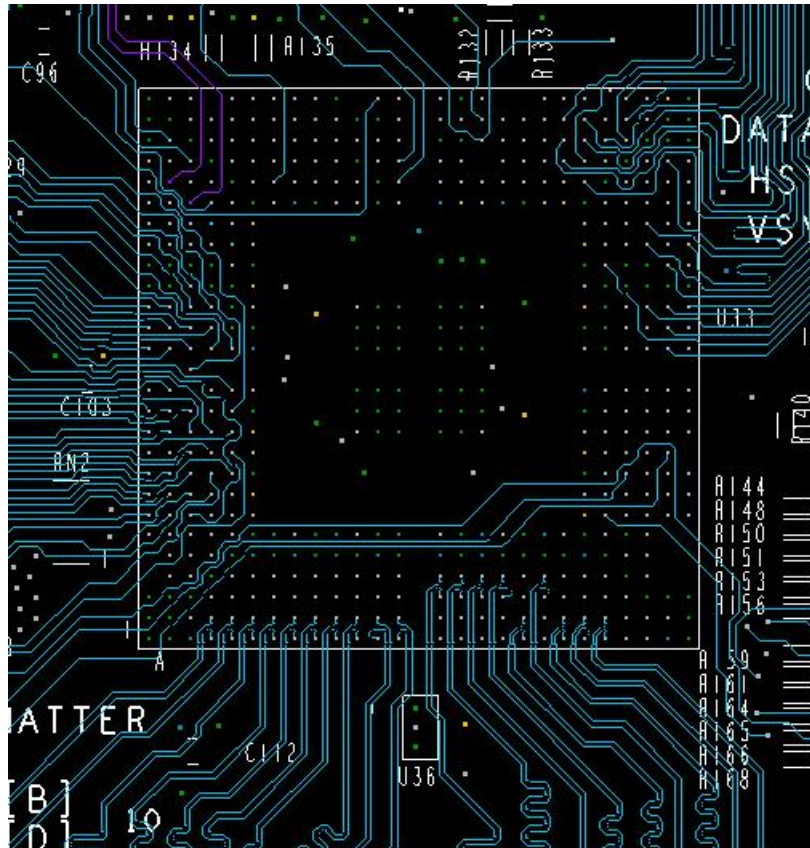


Figure 16. Layer 3

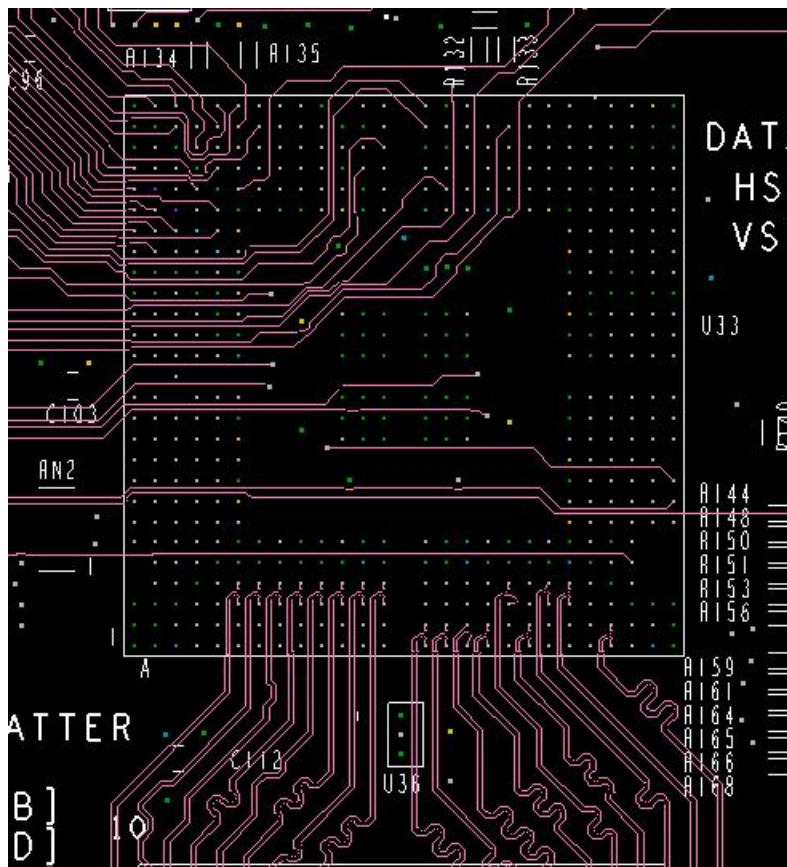


Figure 17. Layer 4

10.1.4 Thermal Considerations

The underlying thermal limitation for the DLPC6421 device is that the maximum operating junction temperature (T_J) not be exceeded (this is defined in the [Recommended Operating Conditions](#)). This temperature is dependent on operating ambient temperature, airflow, PCB design (including the component layout density and the amount of copper used), power dissipation of the DLPC6421 device and power dissipation of surrounding components. The DLPC6421 package is designed primarily to extract heat through the power and ground planes of the PCB, thus copper content and airflow over the PCB are important factors.

The recommended maximum operating ambient temperature (T_A) is provided primarily as a design target and is based on maximum DLPC6421 power dissipation and $R_{\theta JA}$ at 1 m/s of forced airflow, where $R_{\theta JA}$ is the thermal resistance of the package as measured using a JEDEC defined standard test PCB. This JEDEC test PCB is not necessarily representative of the DLPC6421 PCB, and thus the reported thermal resistance may not be accurate in the actual product application. Although the actual thermal resistance may be different, it is the best information available during the design phase to estimate thermal performance. However, after the PCB is designed and the product is built, TI highly recommends that thermal performance be measured and validated.

To do this, the top center case temperature should be measured under the worse case product scenario (max power dissipation, max voltage, max ambient temp) and validated not to exceed the maximum recommended case temperature (T_C). This specification is based on the measured ϕ_{JT} for the DLPC6421 package and provides a relatively accurate correlation to junction temperature. Note that care must be taken when measuring this case temperature to prevent accidental cooling of the package surface. TI recommends a small (approx 40 gauge) thermocouple. The bead and the thermocouple wire should contact the top of the package and be covered with a minimal amount of thermally conductive epoxy. The wires should be routed closely along the package and the board surface to avoid cooling the bead through the wires.

11 Device and Documentation Support

11.1 Device Support

11.1.1 Video Timing Parameter Definitions

- **Active Lines Per Frame (ALPF)** - Defines the number of lines in a Frame containing displayable data: ALPF is a subset of the TLPF.
- **Active Pixels Per Line (APPL)** - Defines the number of pixel clocks in a line containing displayable data: APPL is a subset of the TPPL.
- **Horizontal Back Porch Blanking (HBP)** - Number of blank pixel clocks after Horizontal Sync but before the first active pixel. Note: HBP times are reference to the leading (active) edge of the respective sync signal.
- **Horizontal Front Porch Blanking (HFP)** - Number of blank pixel clocks after the last active pixel but before Horizontal Sync.
- **Horizontal Sync (HS)** – Timing reference point that defines the start of each horizontal interval (line). The absolute reference point is defined by the “active” edge of the HS signal. The “active” edge (either rising or falling edge as defined by the source) is the reference from which all Horizontal Blanking parameters are measured.
- **Total Lines Per Frame (TLPF)** - Defines the Vertical Period (or Frame Time) in lines: TLPF = Total number of lines per frame (active and inactive).
- **Total Pixel Per Line (TPPL)** - Defines the Horizontal Line Period in pixel clocks: TPPL = Total number of pixel clocks per line (active and inactive).
- **Vertical Back Porch Blanking (VBP)** - Number of blank lines after Vertical Sync but before the first active line.
- **Vertical Front Porch Blanking (VFP)** - Number of blank lines after the last active line but before Vertical Sync.
- **Vertical Sync (VS)** - Timing reference point that defines the start of the vertical interval (frame). The absolute reference point is defined by the “active” edge of the VS signal. The “active” edge (either rising or falling edge as defined by the source) is the reference from which all Vertical Blanking parameters are measured.

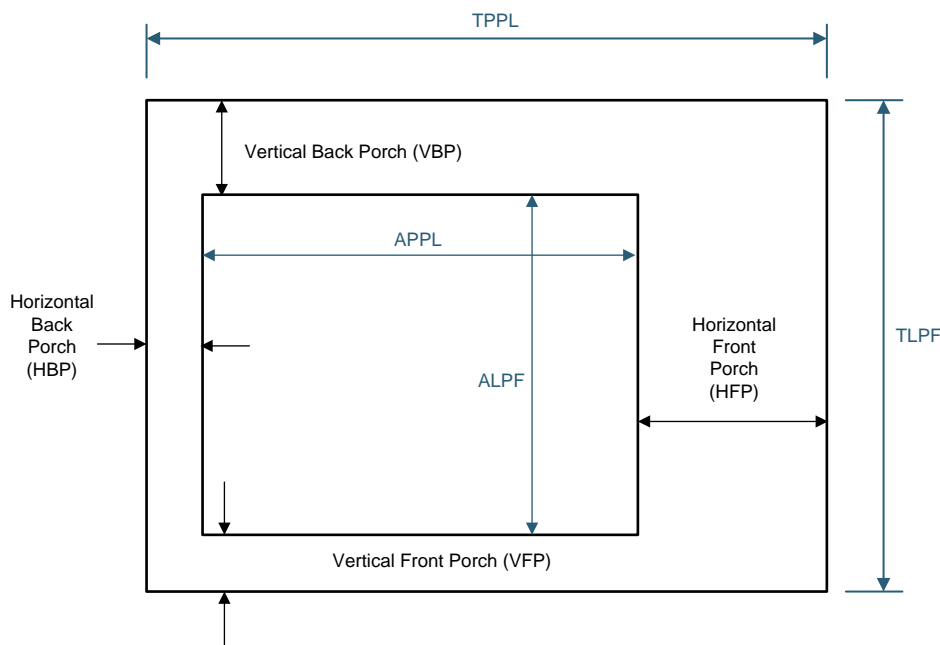


Figure 18. Timing Parameter Diagram

Device Support (continued)

11.1.2 Device Markings

11.1.2.1 Device Marking Description

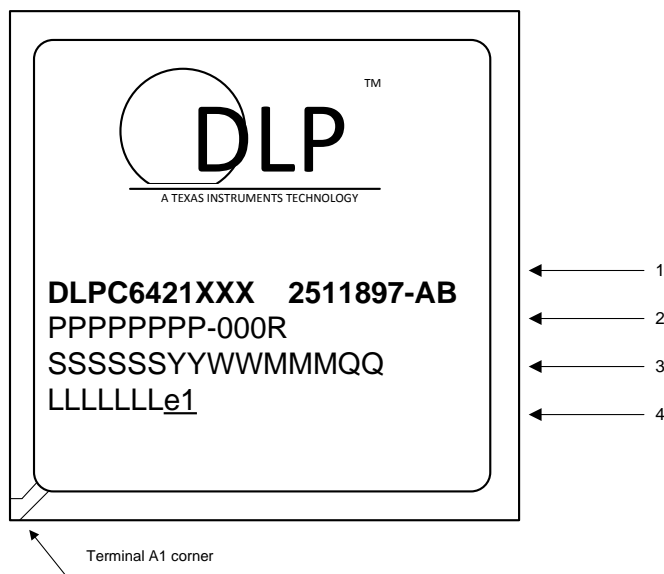


Figure 19. DLPC6421 Device Markings

Marking Definitions:

Line1: DLP Device Name followed by TI Part Number

- XXX: ZPC Device Name Marking

Line2: Foundry part number

Line3: SSSSSSYWWMMM-QQ Package Assembly information

- SSSSSS: Manufacturing Country
- YYWW: Date Code (YY = Year :: WW = Week)
- MMM: Manufacturing Site (HAL = Taiwan, HBL = Japan)
- QQ: Qualification level

Line4: LLLLLLLe1 Manufacturing Information

- LLLLLL: Manufacturing Lot code
- e1: lead-free solder balls consisting of SnAgCu

11.2 Documentation Support

11.2.1 Related Documentation

The following documents contain additional information related to the chipset components used with the DLPC6421:

- [DLP470TP DMD Datasheet](#)
- [DLPA3000 Power Management and LED Driver Datasheet](#)
- [DLPA3005 Power Management and LED Driver Datasheet](#)

11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks

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DLP is a registered trademark of Texas Instruments.

11.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

12.1 Package Option Addendum

12.1.1 Packaging Information

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾	Op Temp (°C)	Device Marking ⁽⁴⁾⁽⁵⁾
DLPC6421ZPC	ACTIVE	BGA	ZPC	516	1	TBD	Call TI	Level-3-255C-168 HRS		

- (1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PRE_PROD Unannounced device, not in production, not available for mass market, nor on the web, samples not available.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.
- (2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)
- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device
- (5) Multiple Device markings will be inside parentheses. Only on Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
DLPC6421ZPC	ACTIVE	BGA	ZPC	516	60	TBD	Call TI	Call TI			Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

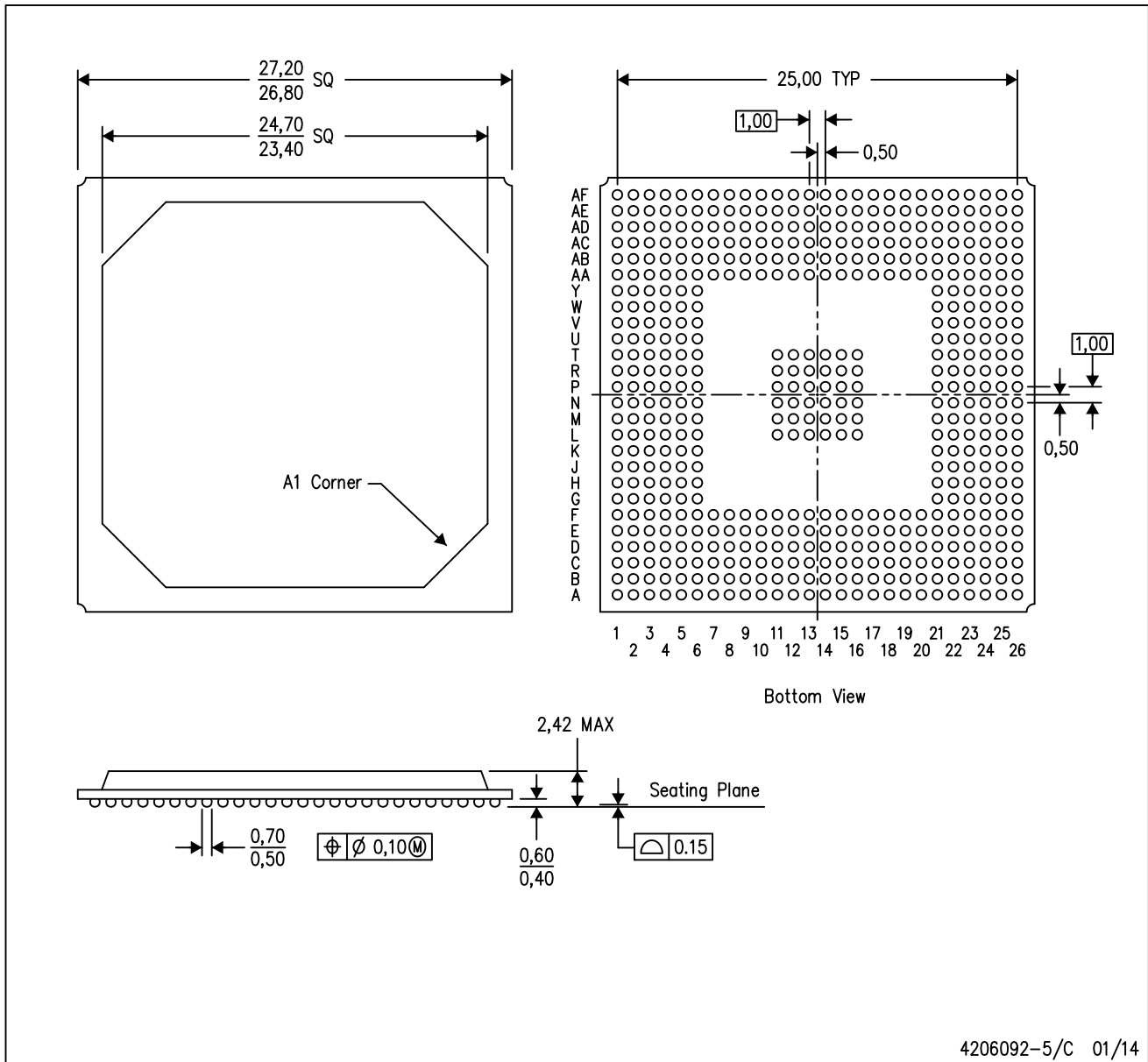
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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ZPC (S-PBGA-N516)

PLASTIC BALL GRID ARRAY



4206092-5/C 01/14

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. This package is Pb-free.

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